

EUDET HCAL Electronics Integration



Riccardo Fabbri

on behalf of the *CALICE* Collaboration



ECFA 2008

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-
- ❖ **Physics Motivation and Design Constraints**
 - ❖ **SPIROC Chip**
 - ❖ **HCAL Base Units**
 - ❖ **HCAL Endcap Board**
 - ❖ **Time Schedule**
 - ❖ **Conclusions and Outlook**
-

Physics Requirements and Design Constraint

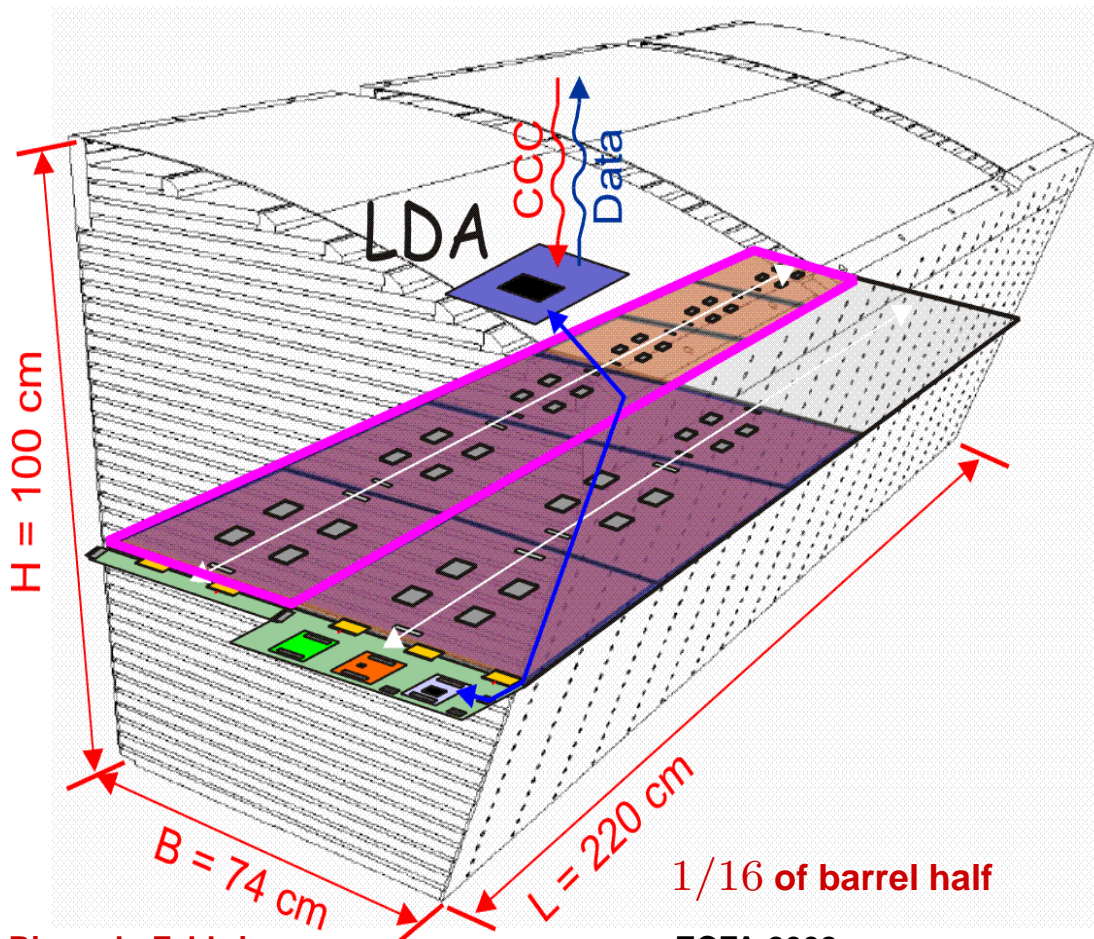
- Integration of Electronics into Analogue Hadronic Calorimeter (HCAL) for ILC
- Thousand of channels to be handled (high-granularity calorimeter)
 - ⇒ physics motivation: particle data flow
- Non-invasive integration needed; as close as possible to active area in detector

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 - ⇒ **physics motivation: particle data flow**
- **Non-invasive integration needed; as close as possible to active area in detector**
 - ⇒ **compact design with integrated sensors & electronics**
 - minimum dead areas
 - minimum power consumption
 - maximum compactification

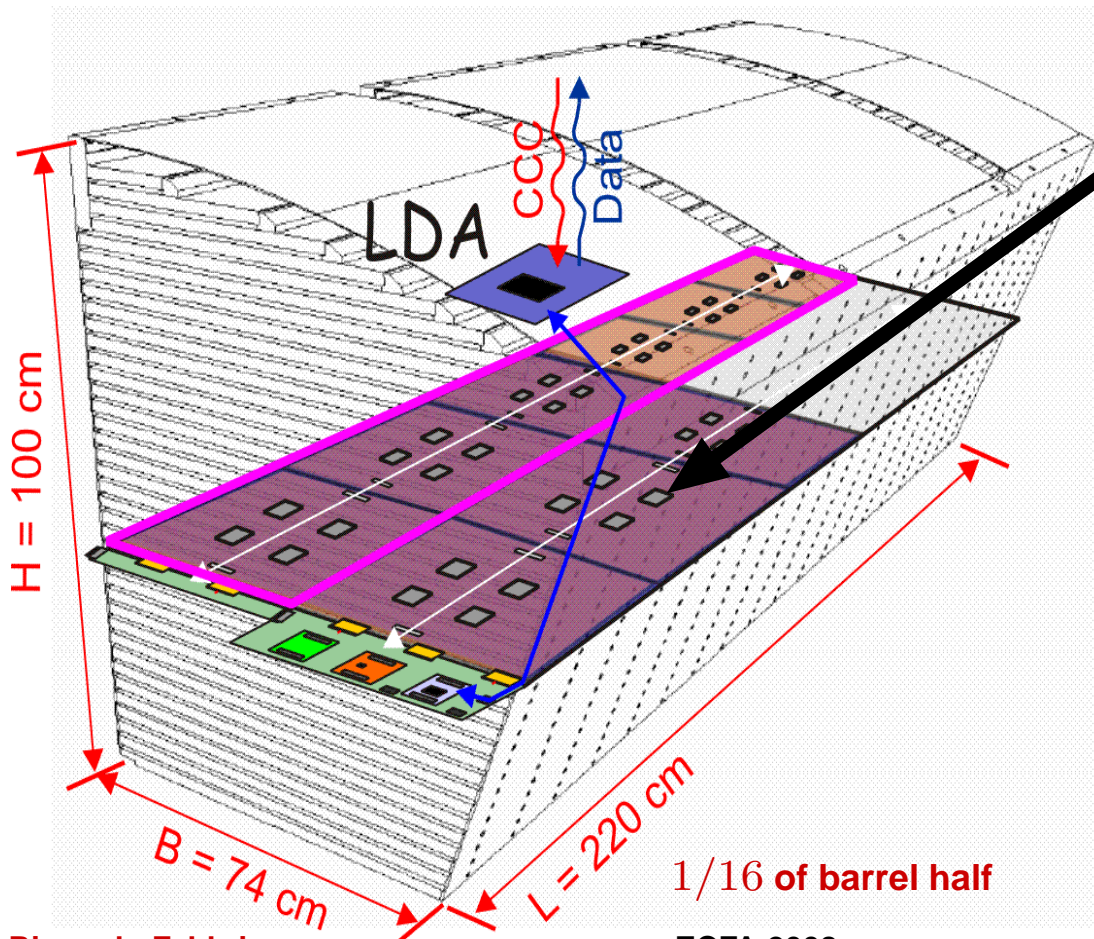
Design Proposal

- Barrel of HCAL architecture:**
- scintillator-based calorimeter
 - granularity: $3 \times 3 \text{ cm}^2$ tiles
 - SiPM readout (one per tile)



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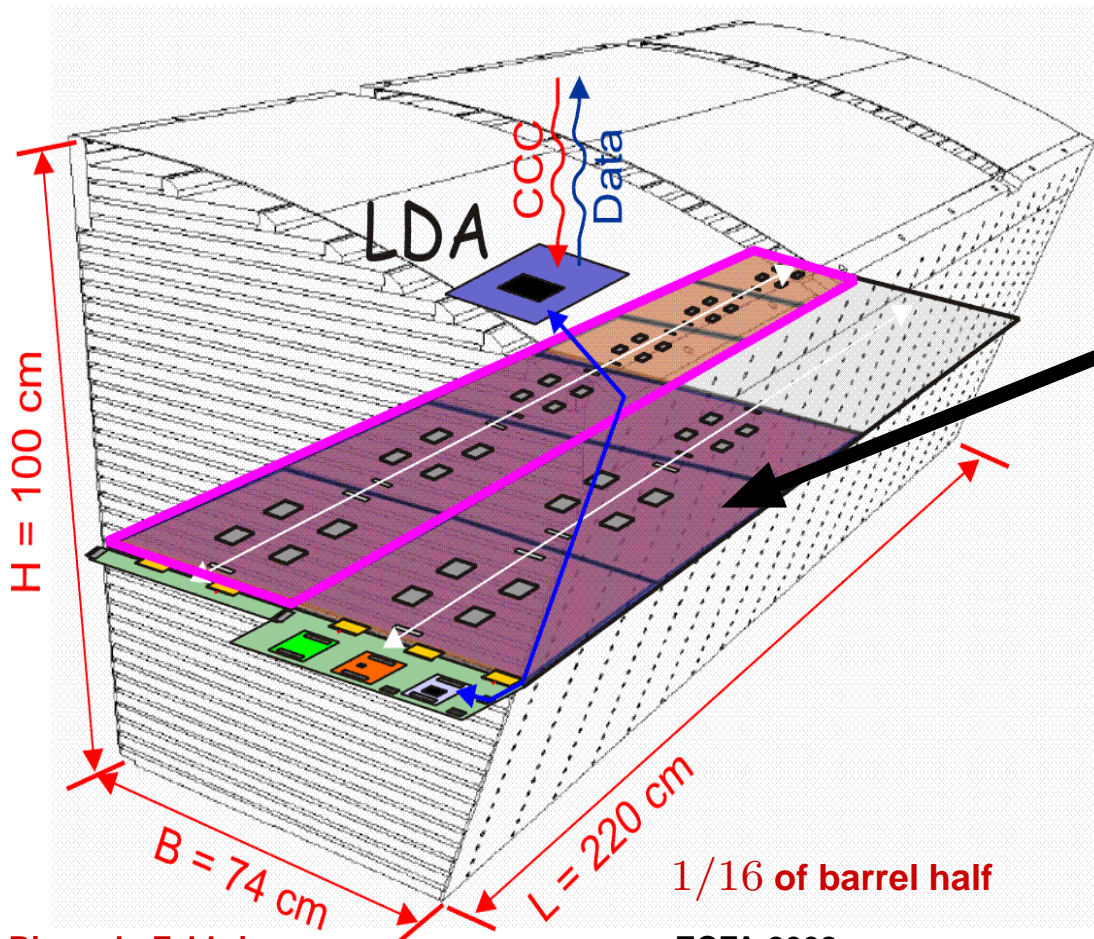
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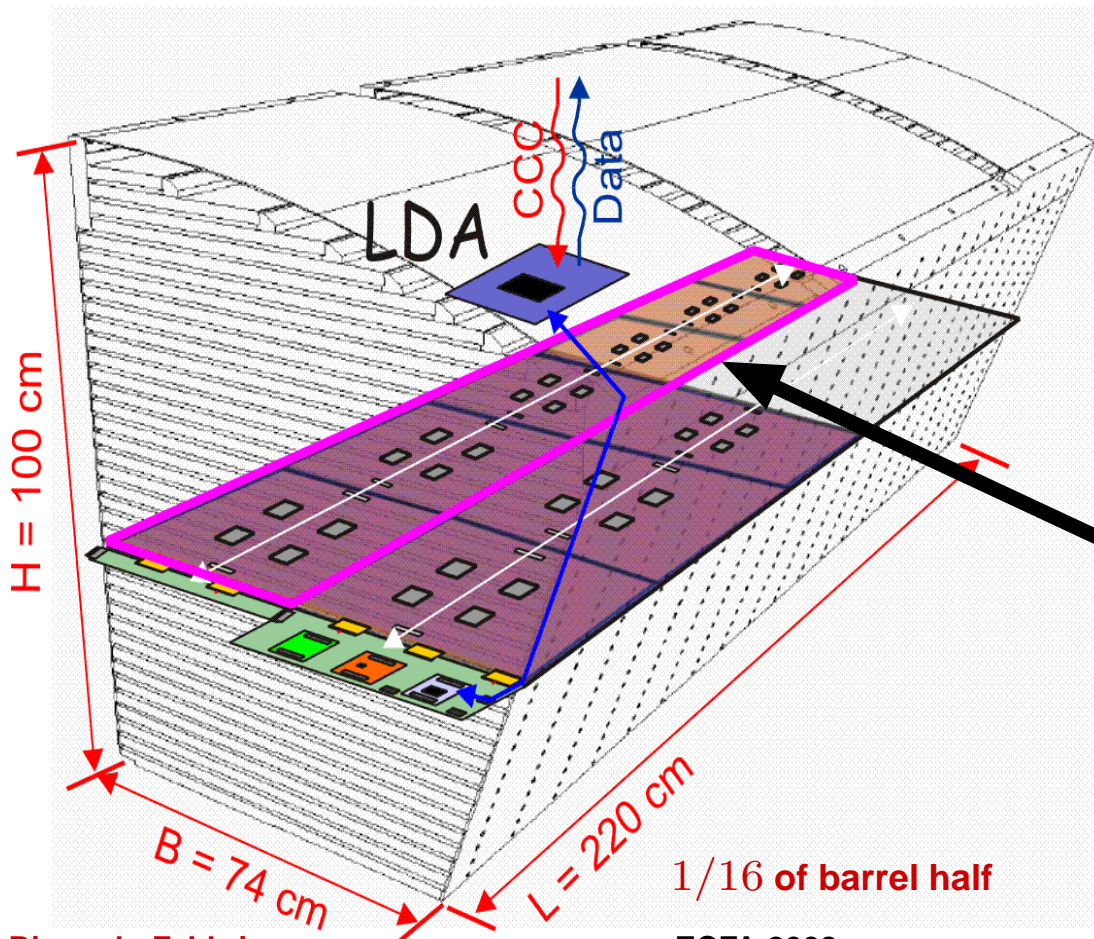
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hosts up to 12×12 tiles/4SPIROCs

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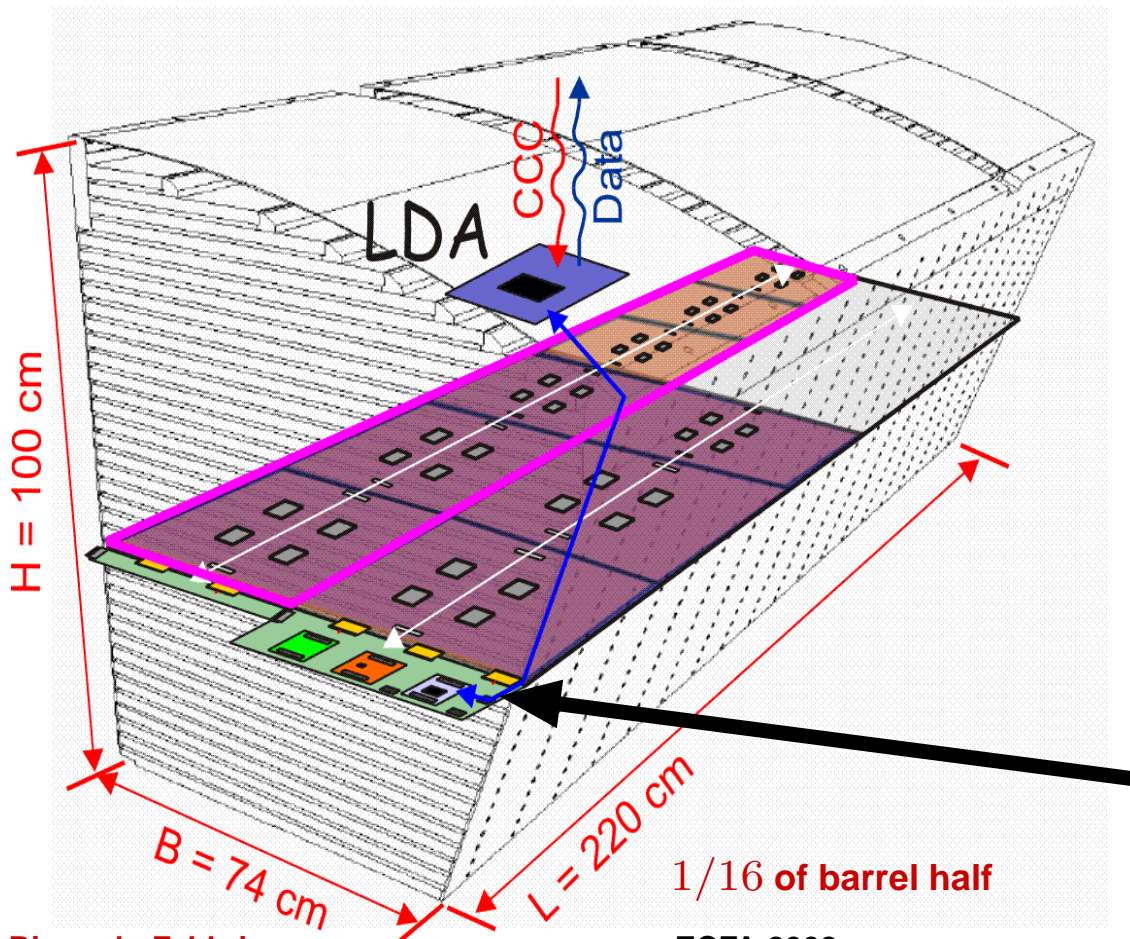
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hosts 6 HBUs in a row

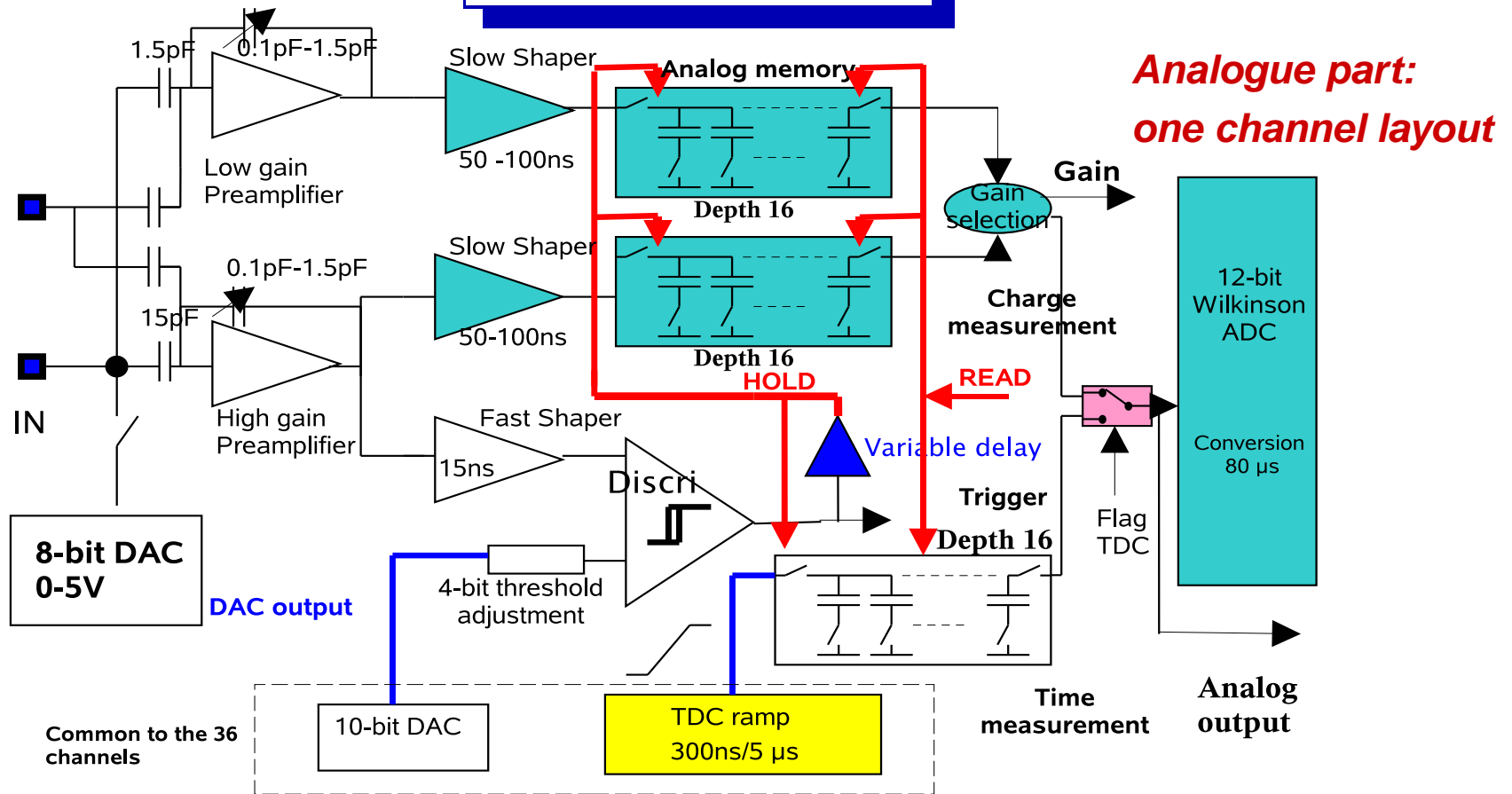
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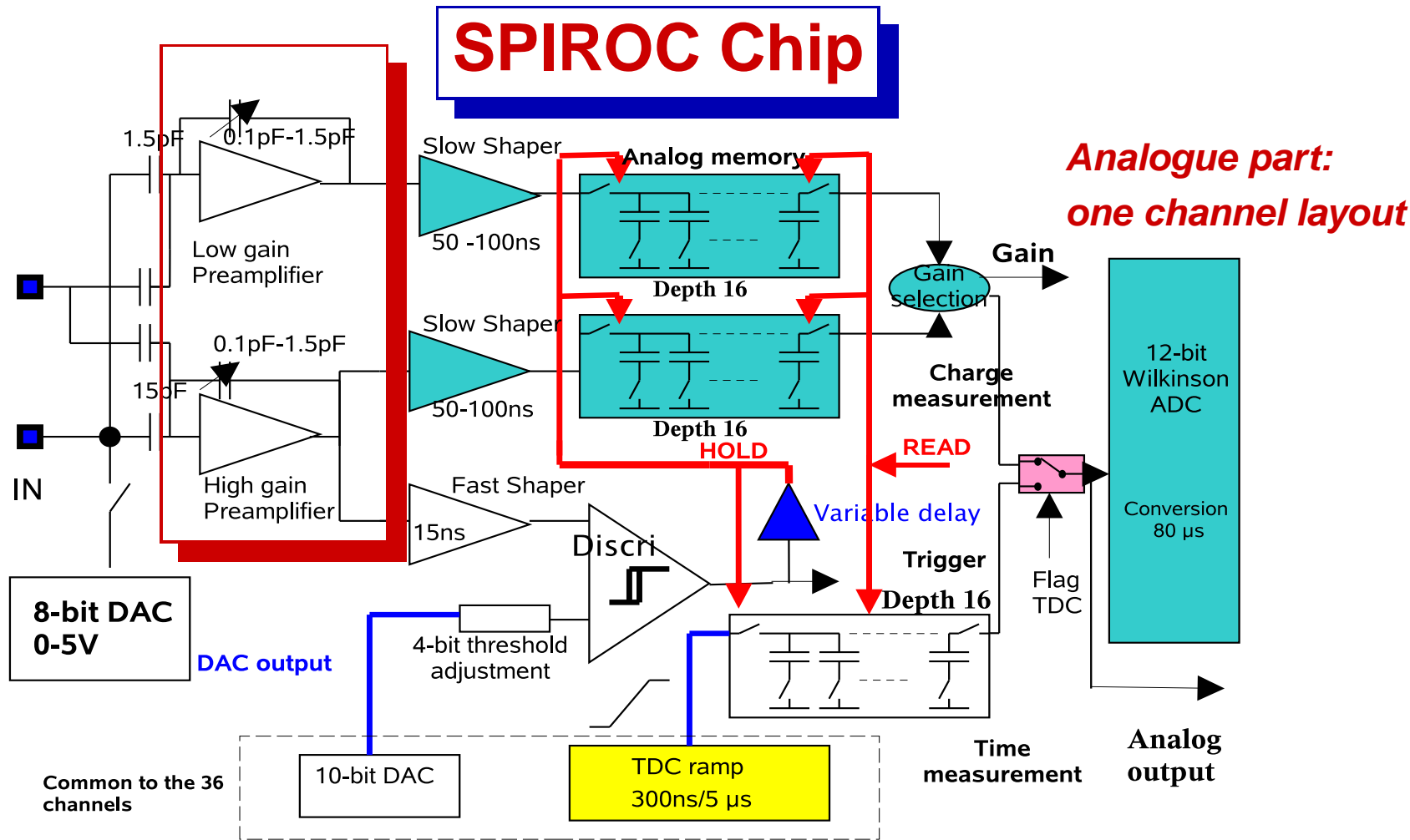
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- **HEB (HCAL Endcap Board):**
hosts *DIF CALIB POWER* modules

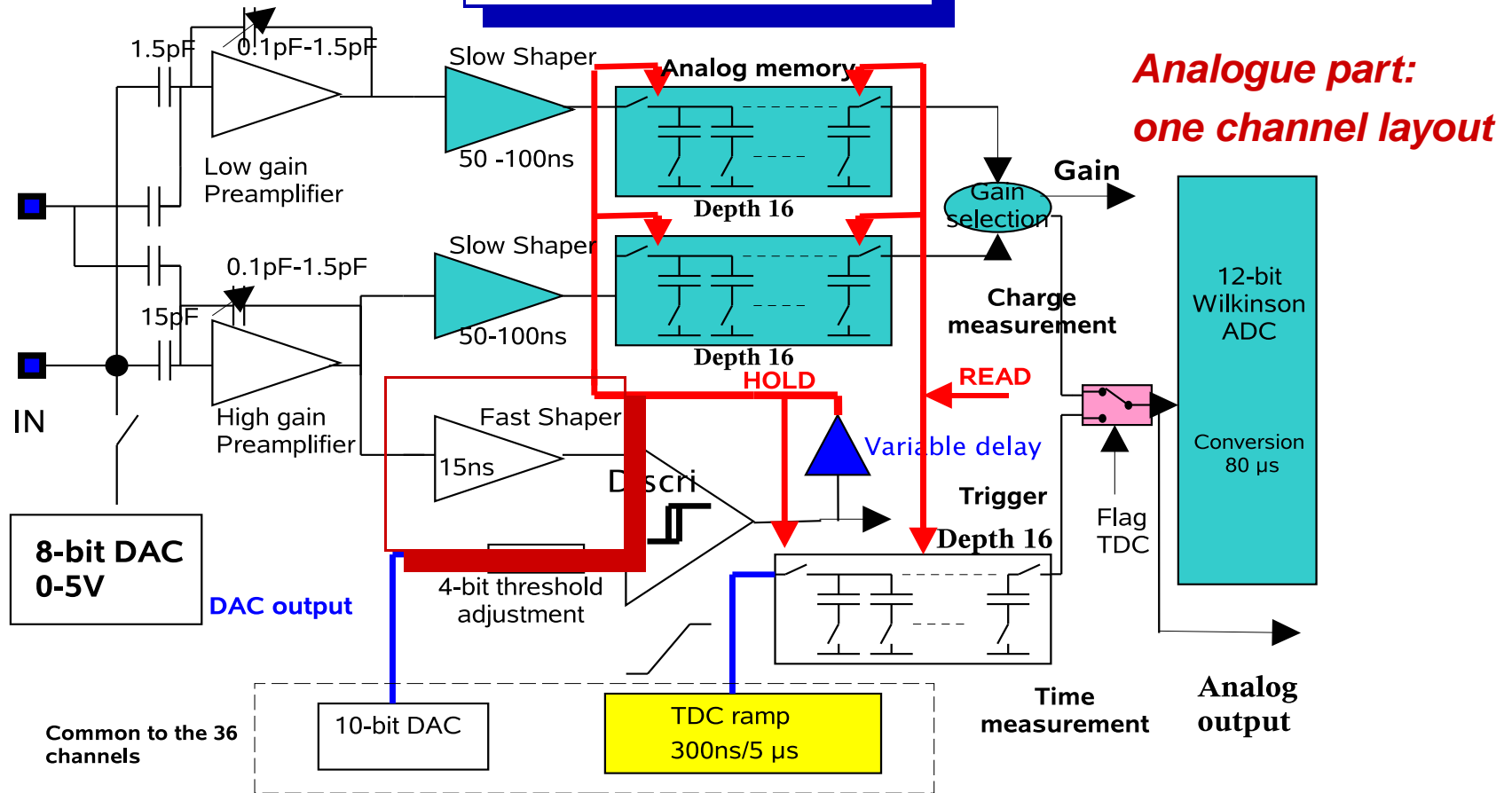
SPIROC Chip





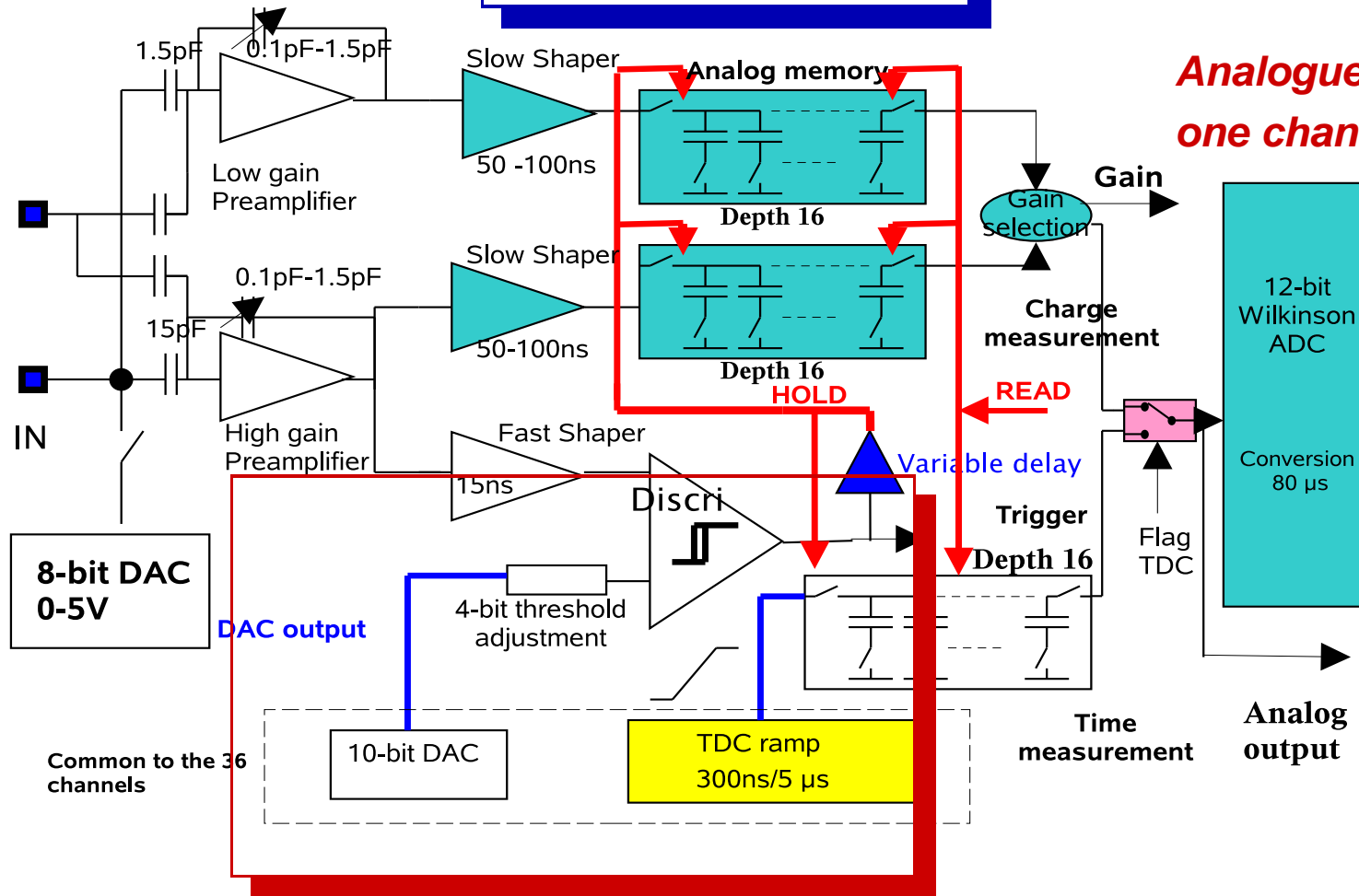
Separate channels for adjustable pre-amplification in low/high gain mode of input signal

SPIROC Chip



fast shaper for ...

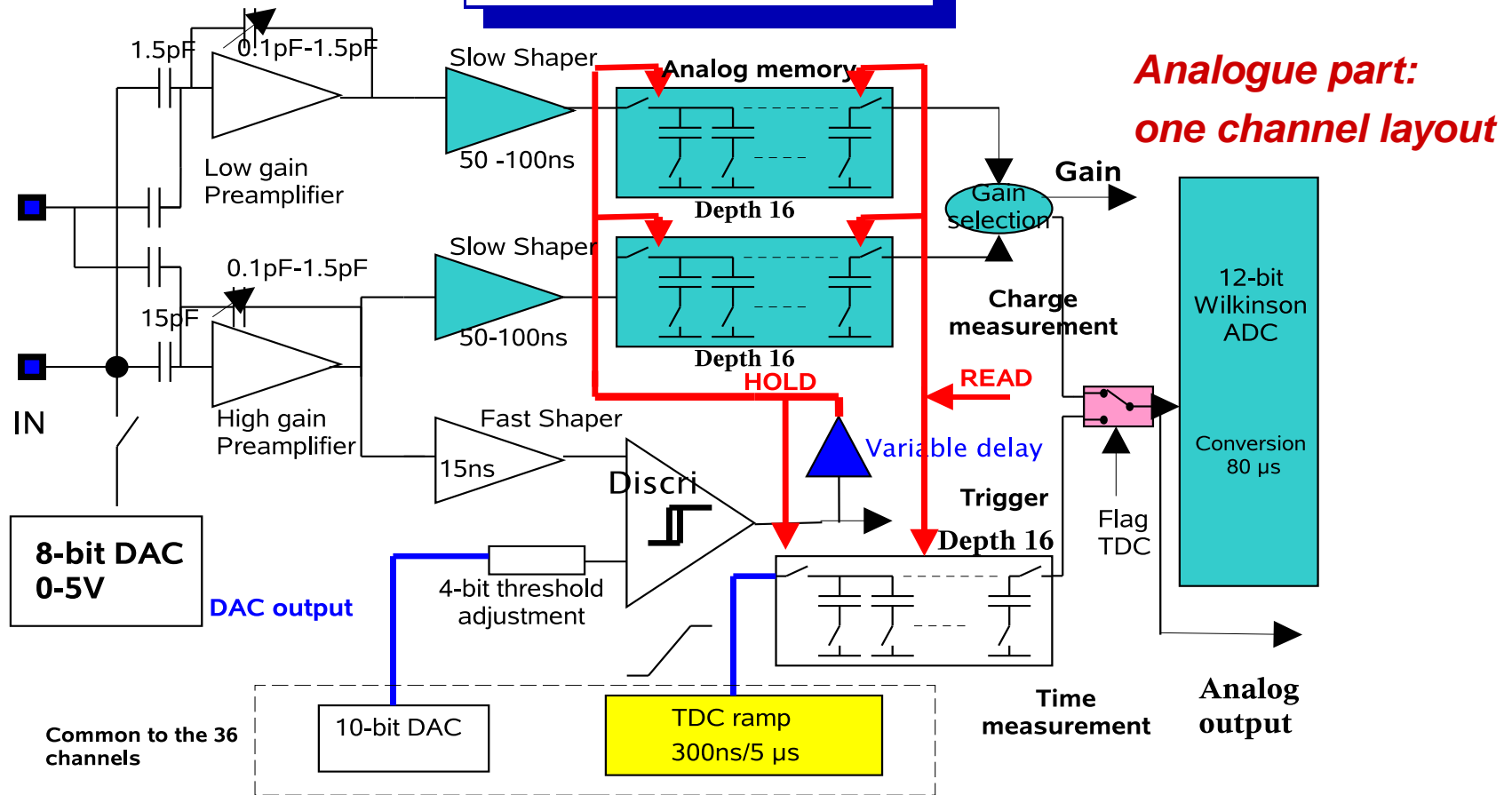
SPIROC Chip



*Analogue part:
one channel layout*

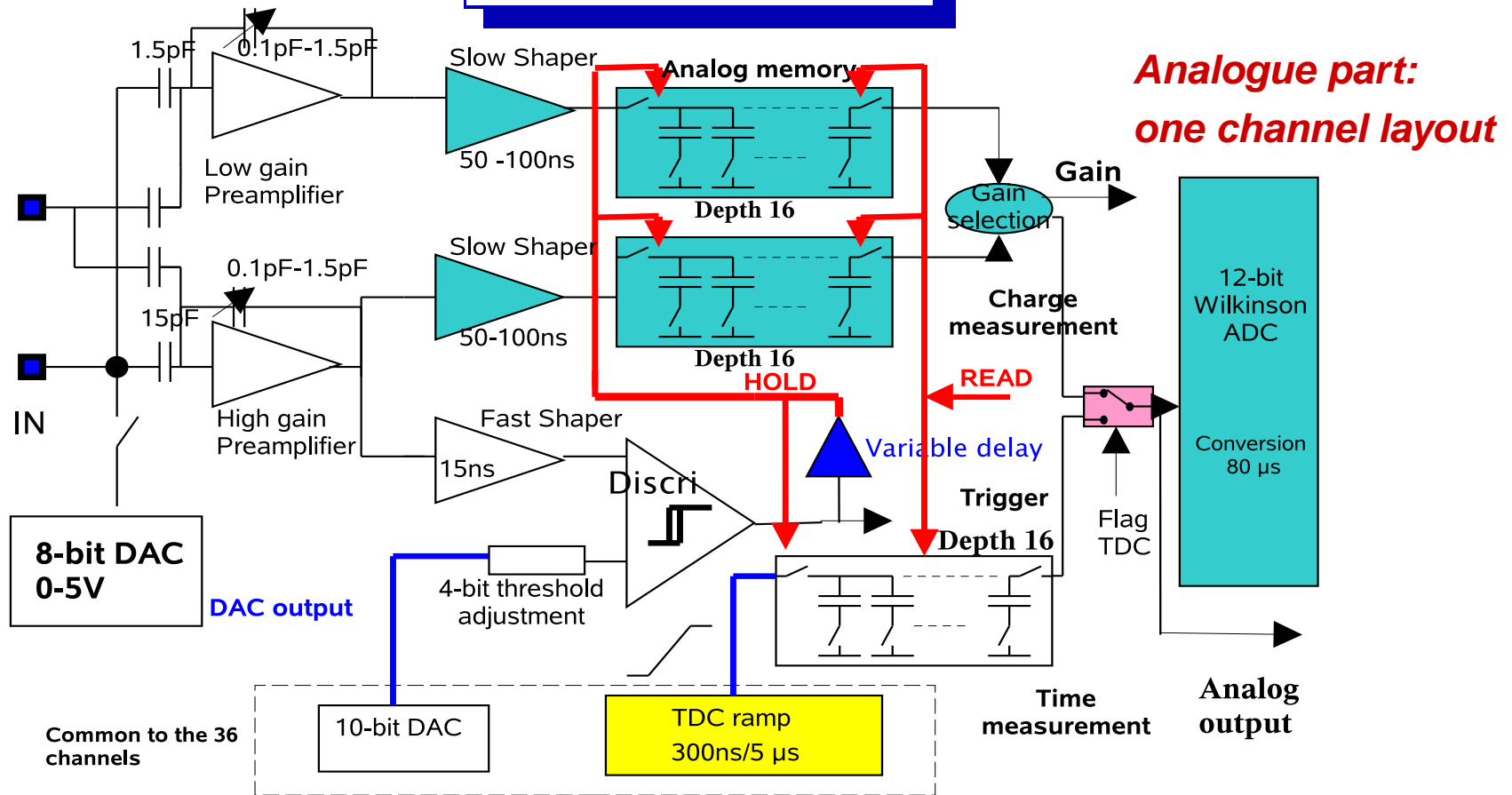
...autotrigger (to eventually hold the analogue shaped signal)

SPIROC Chip



plus digital stage (not shown here) to synchronise acquisition/readout with ILC timing

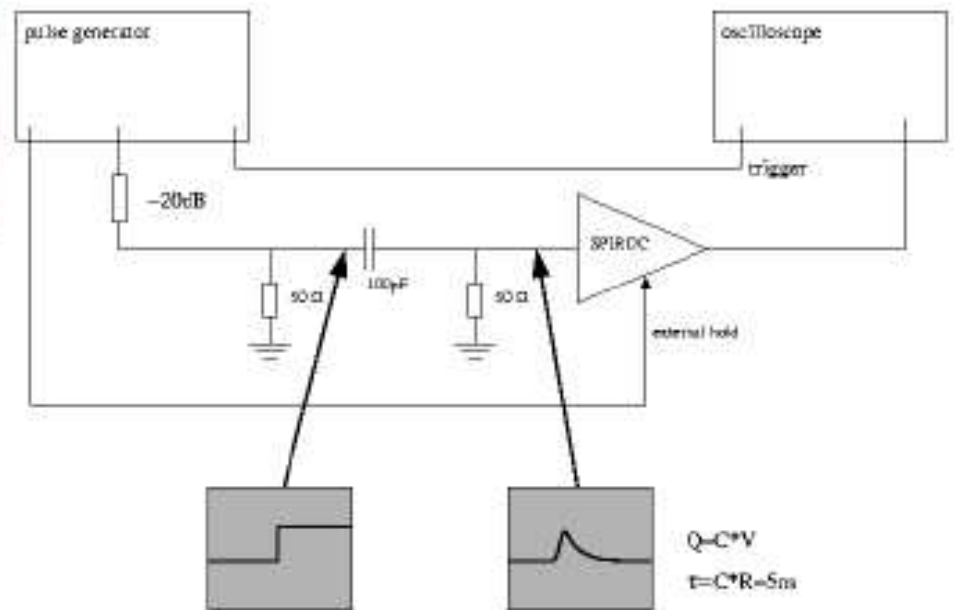
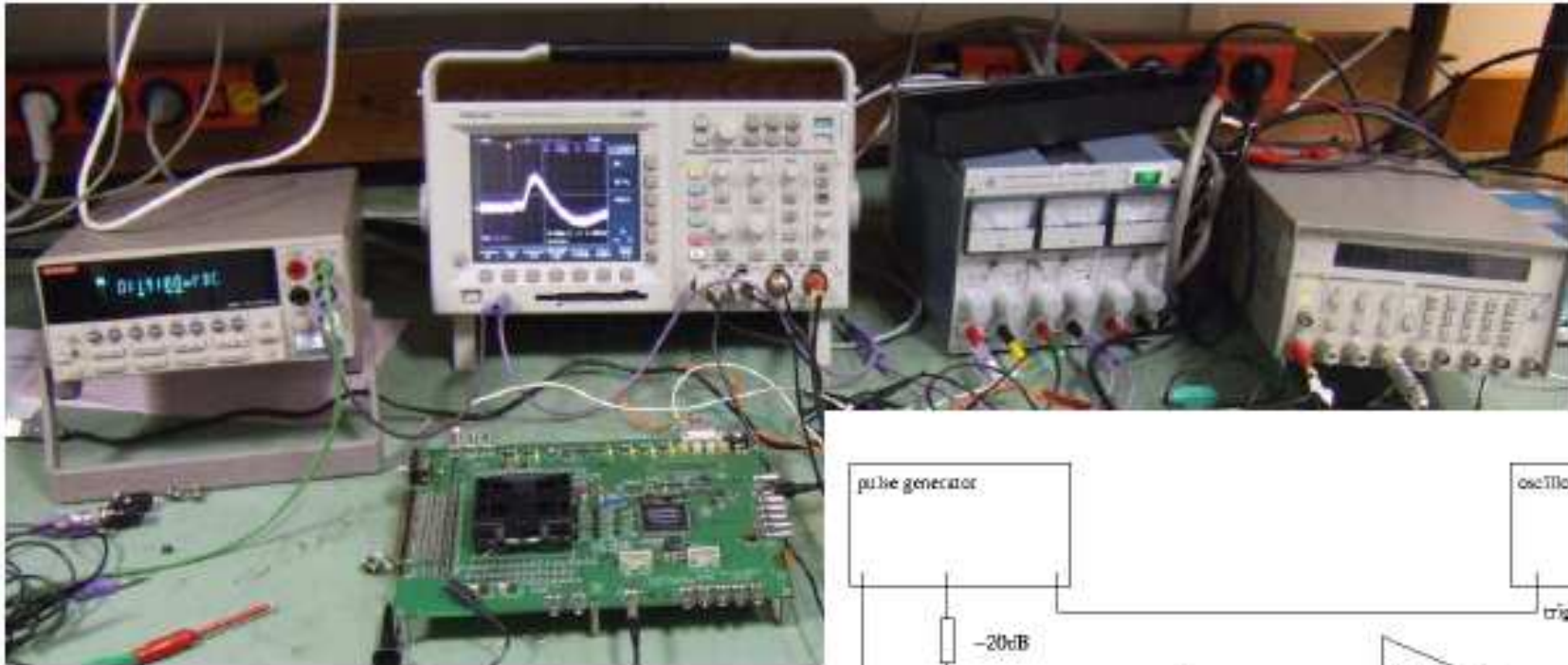
SPIROC Chip



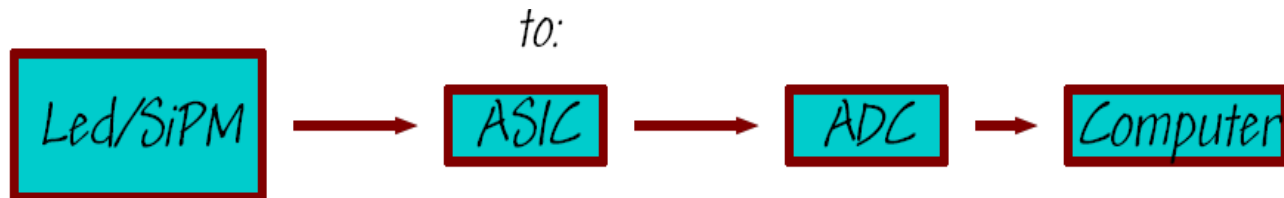
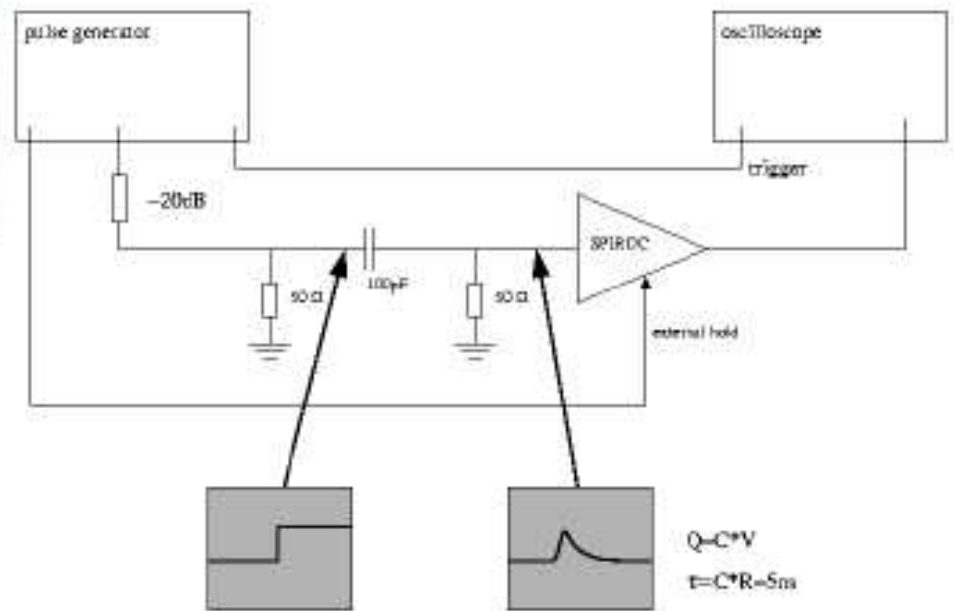
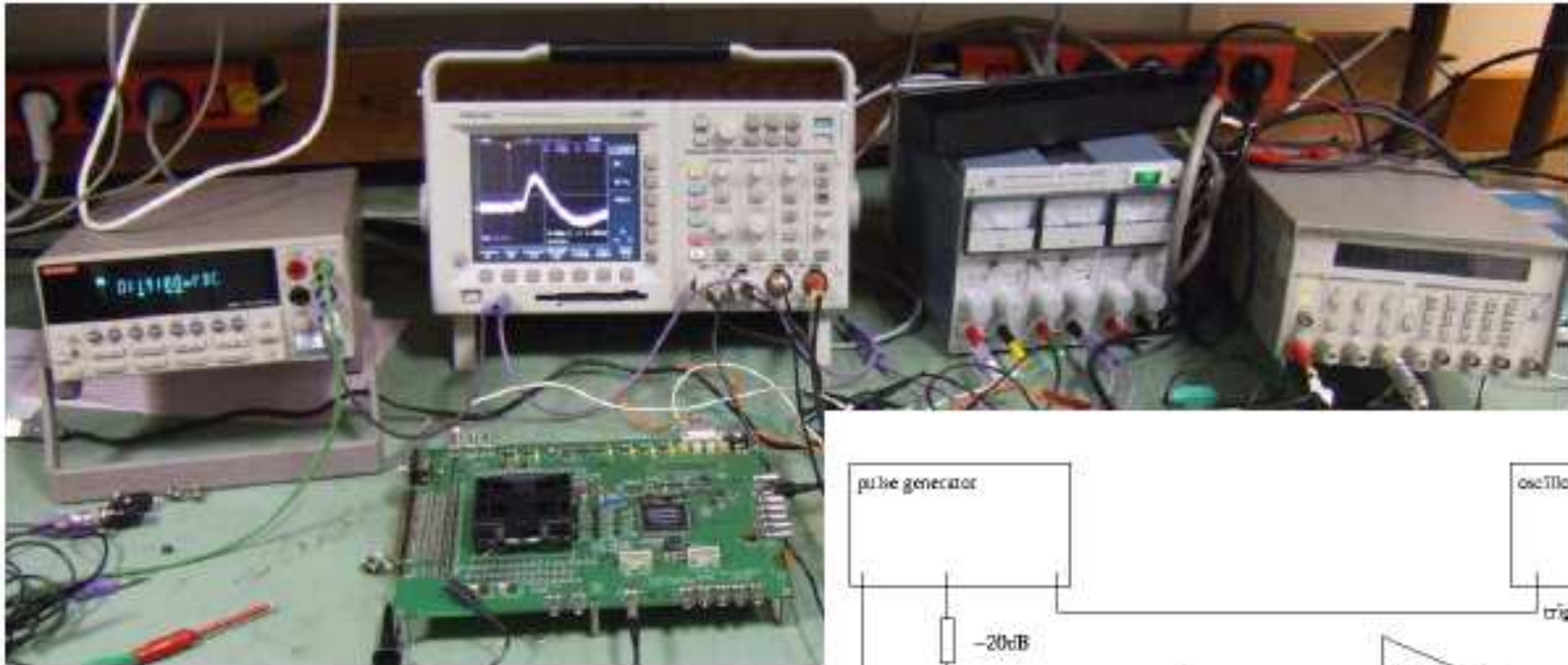
- Designed/developed by LAL (Paris)
- Should handle 36 input signals (→ 36 SiPMs)
- Autotrigger: peak of input signal held by signal itself!
- Commissioning ongoing at DESY, with strong support from LAL and

Heidelberg colleagues

Tests on SPIROC at DESY



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Tests on SPIROC at DESY: status

● Linearity studies in low/high gain mode

⇒ at different shaping-time/variable capacitance

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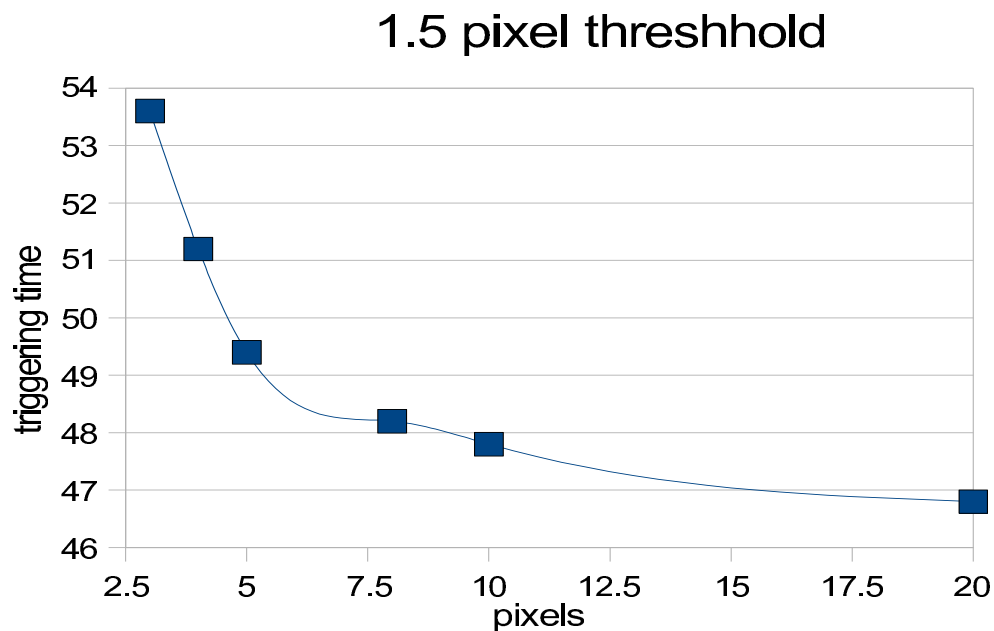
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- **single-photon spectra from SiPM**
 - external trigger (to hold the signal)

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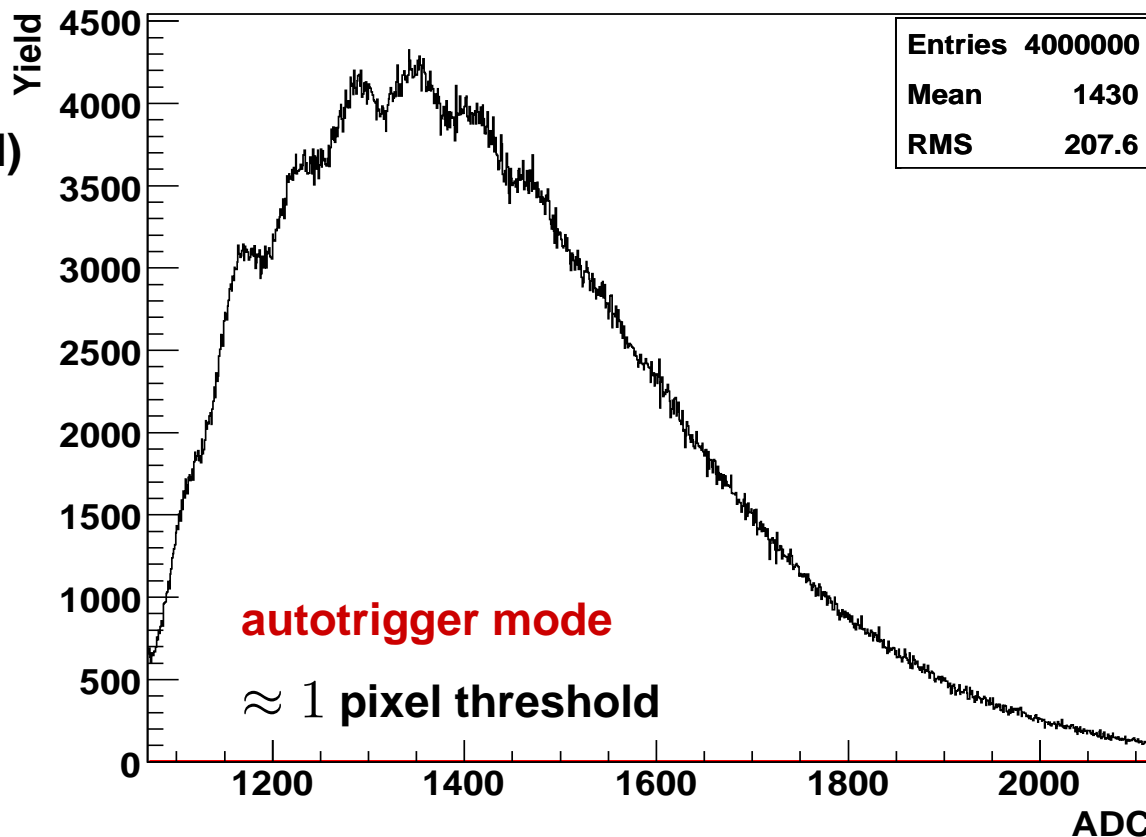
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- **very first** spectra in autotrigger

mode with ad-hoc set-up

⇒ early to draw quantitative conclusions!

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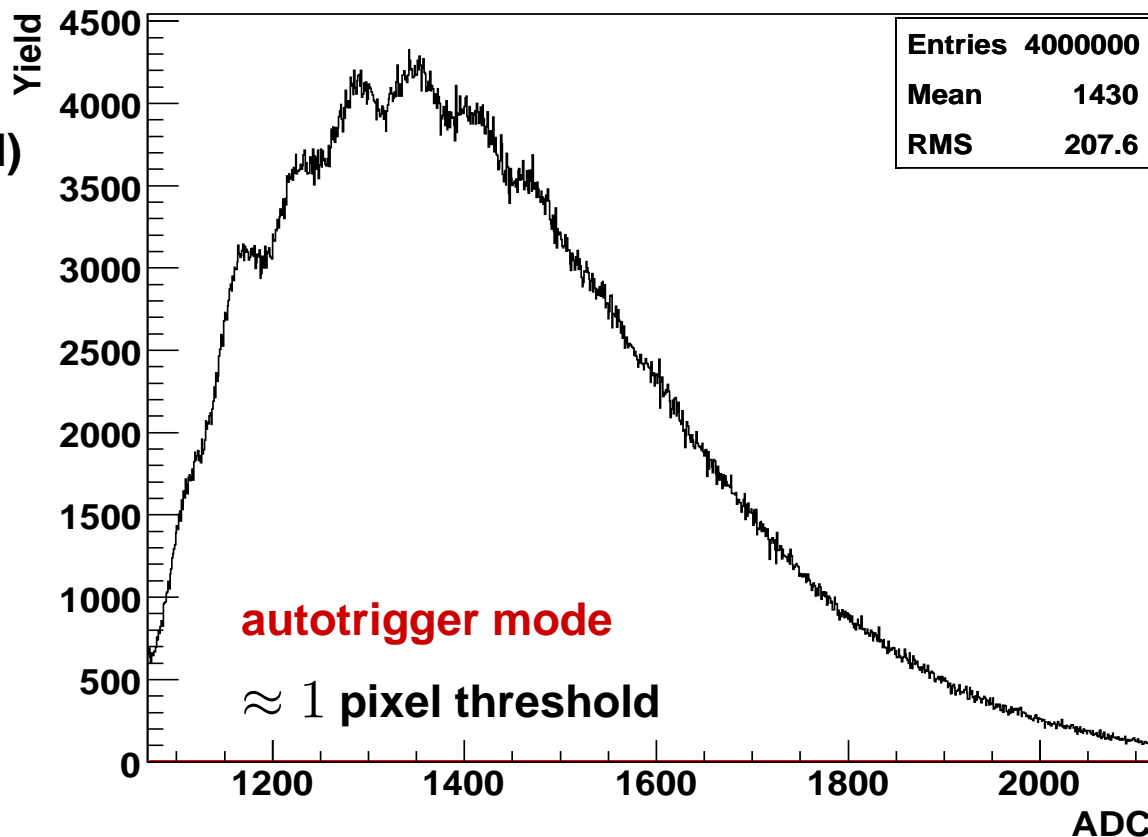
● Improvement foreseen when

- large jitter/time-walk understood

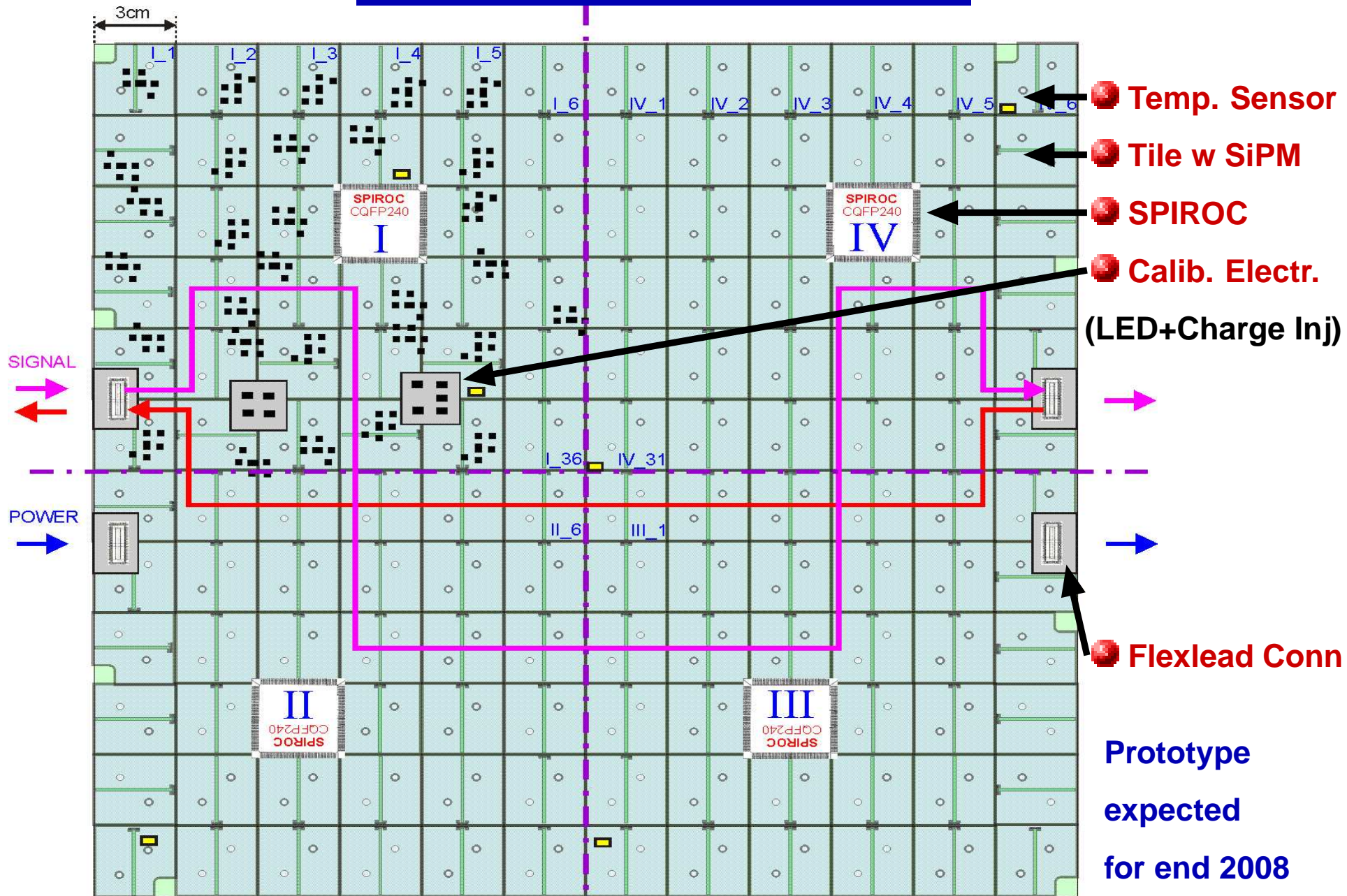
- chip digital part (for autotrigger)

fixed (→ SPIROC2)

Preliminary!



HBU (HCAL Base Unit)

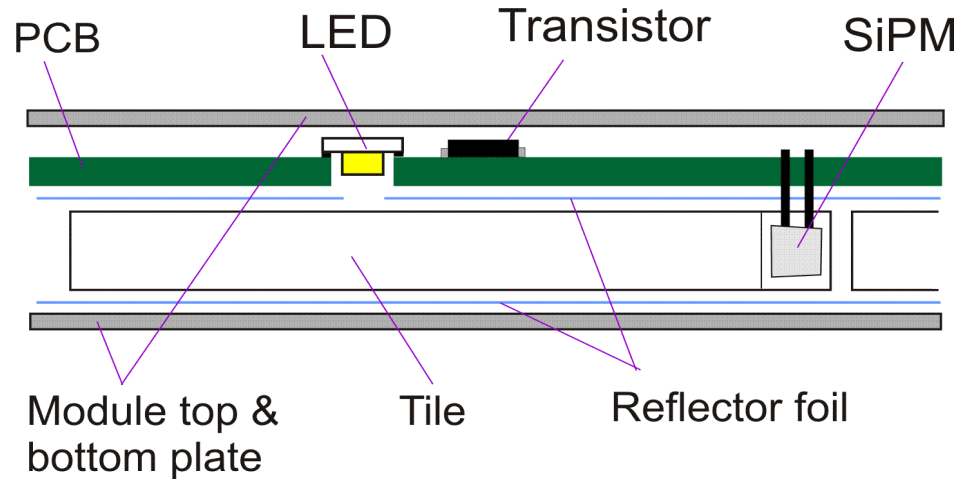


HBU (HCAL Base Unit)

Calibration system

Here shown is concept under investigation at DESY

⇒ Other option available from Praga group (see Polak's talk)



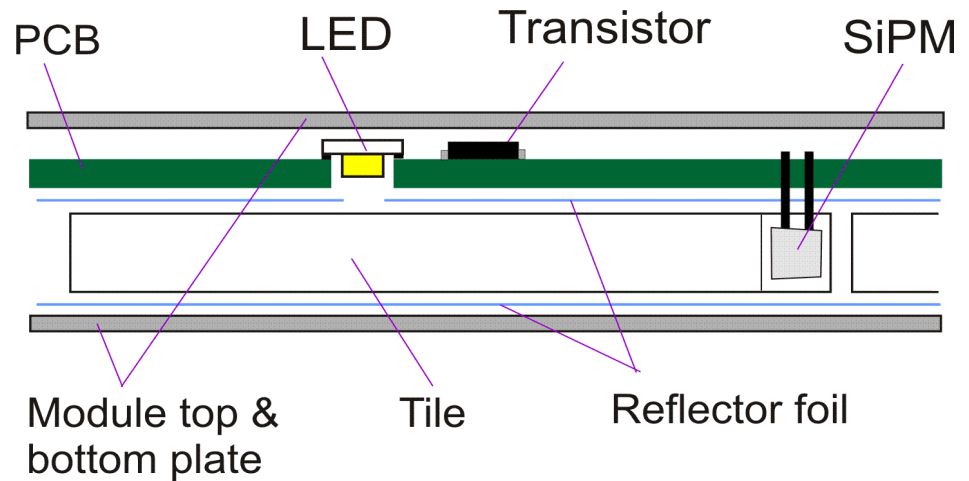
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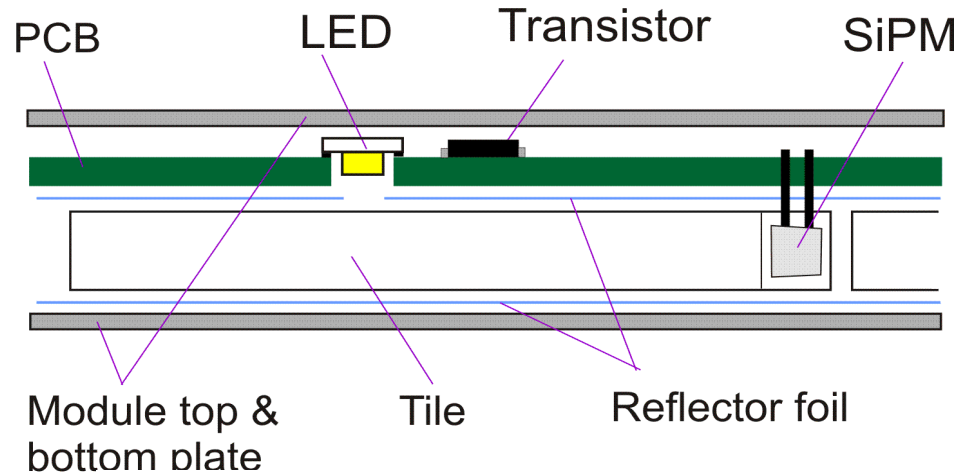
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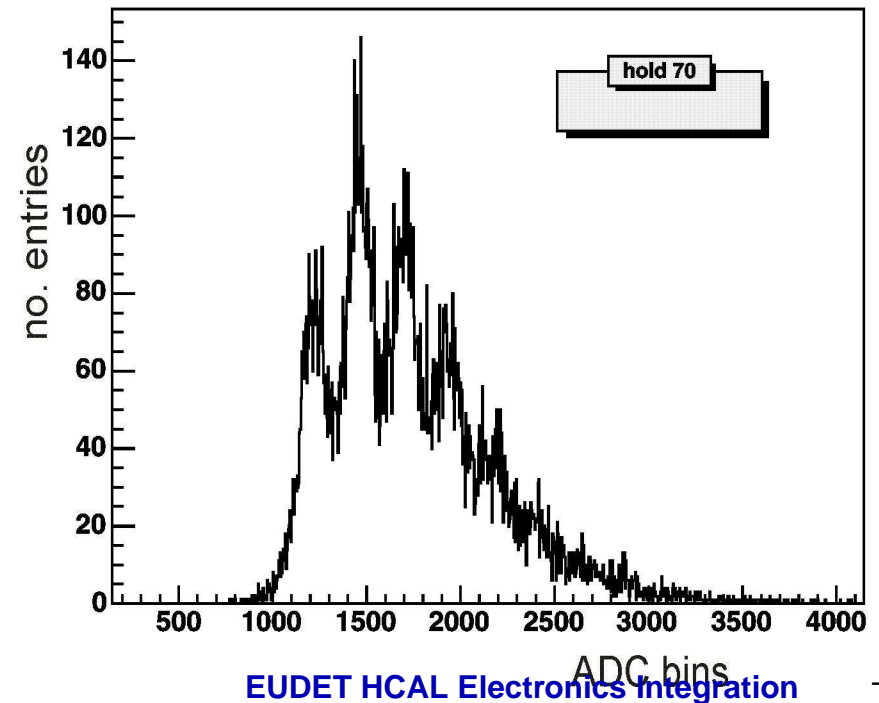
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 - single-photon peak spectrum visible
 - ⇒ LED integration setup suitable



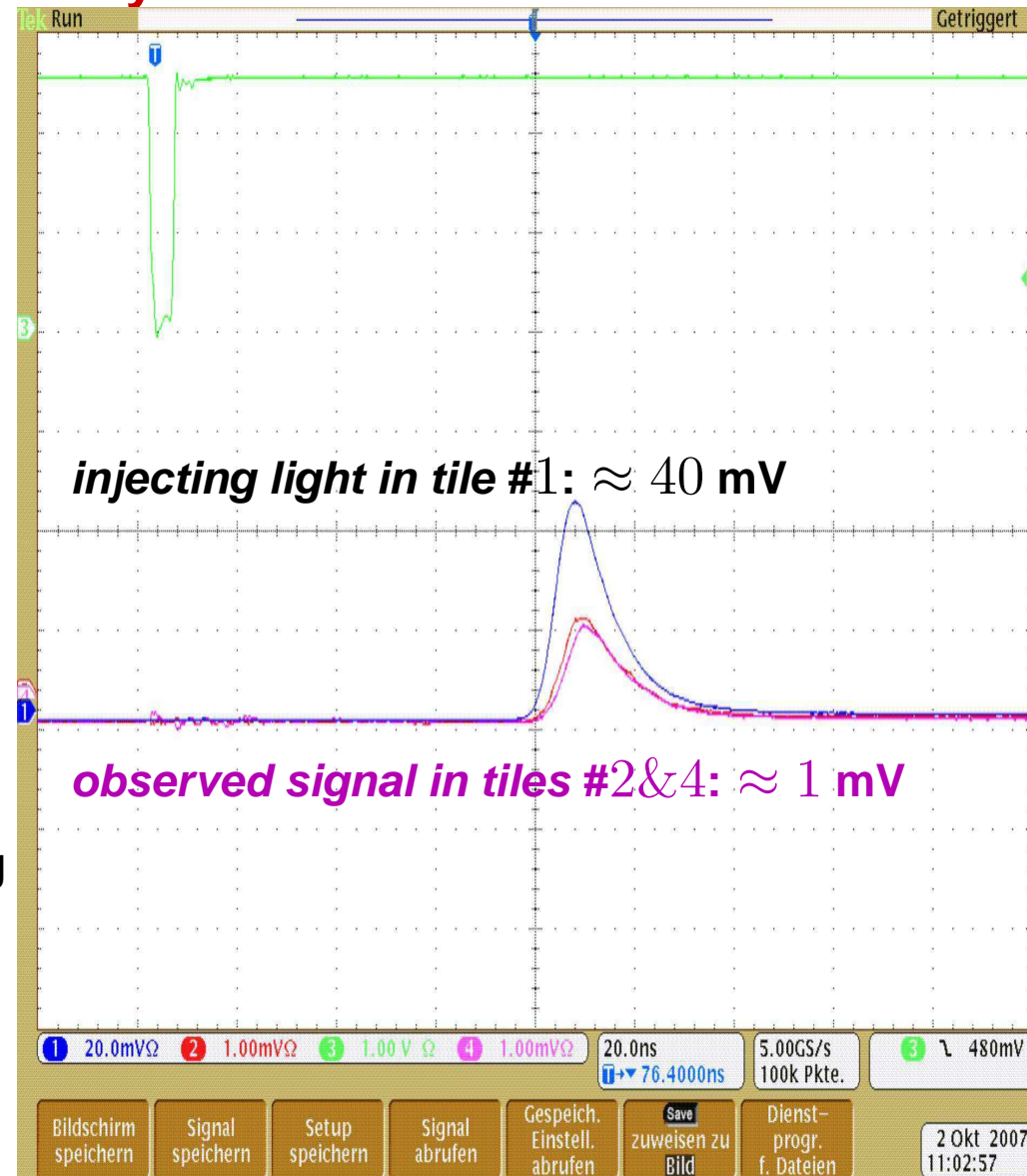
SER002, Slot 12, FE4, Chip 0, Chan 17



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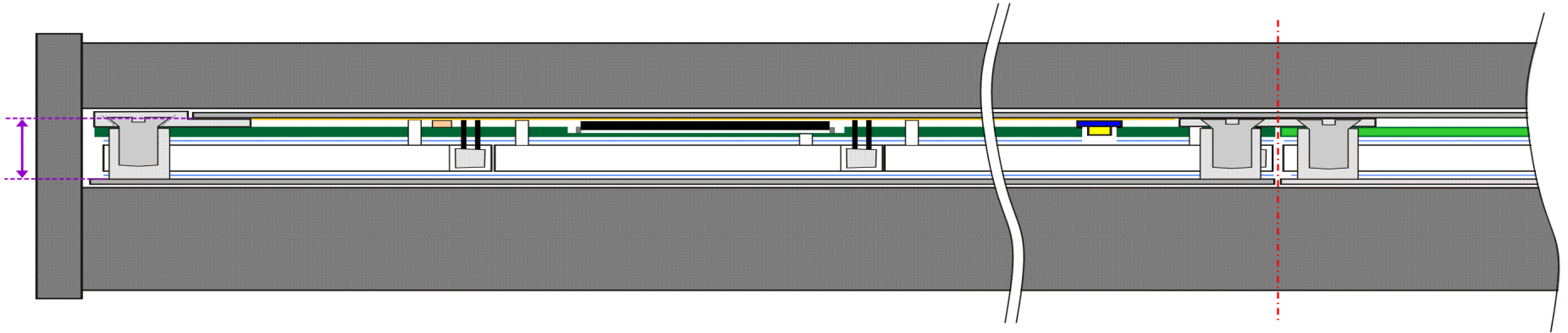
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 - ⇒ LED integration setup suitable
 - cross-talk under investigation
 - $\text{cross-talk} \approx 2.5\%$
 - ⇒ possibly due to tile-tile coupling



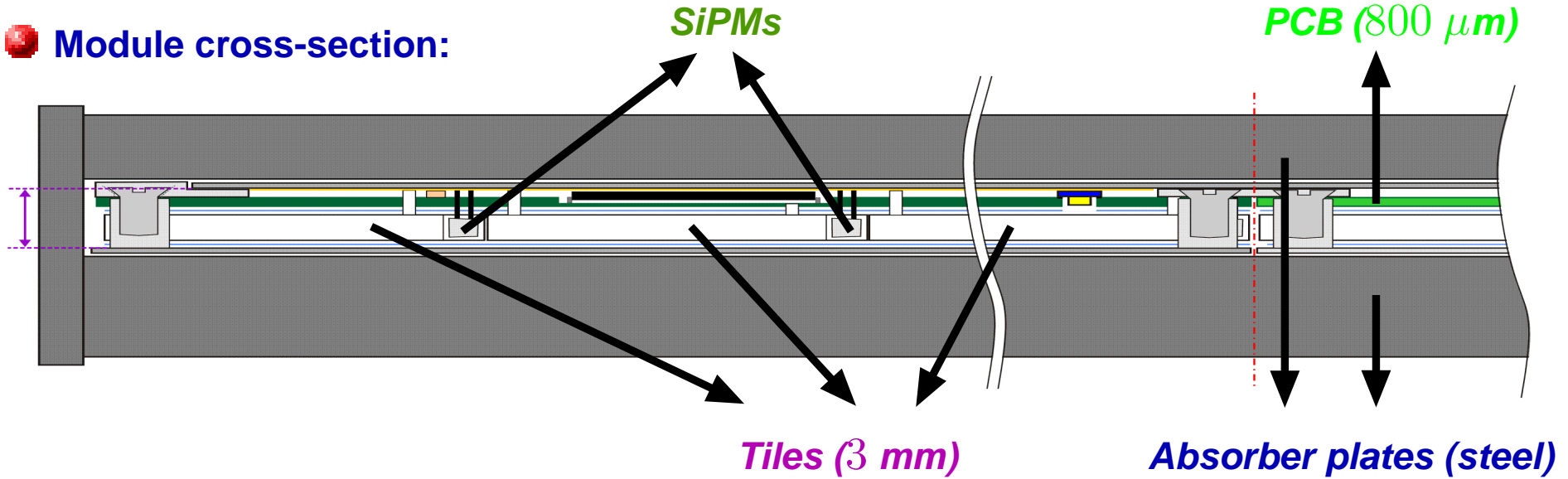
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Module cross-section:



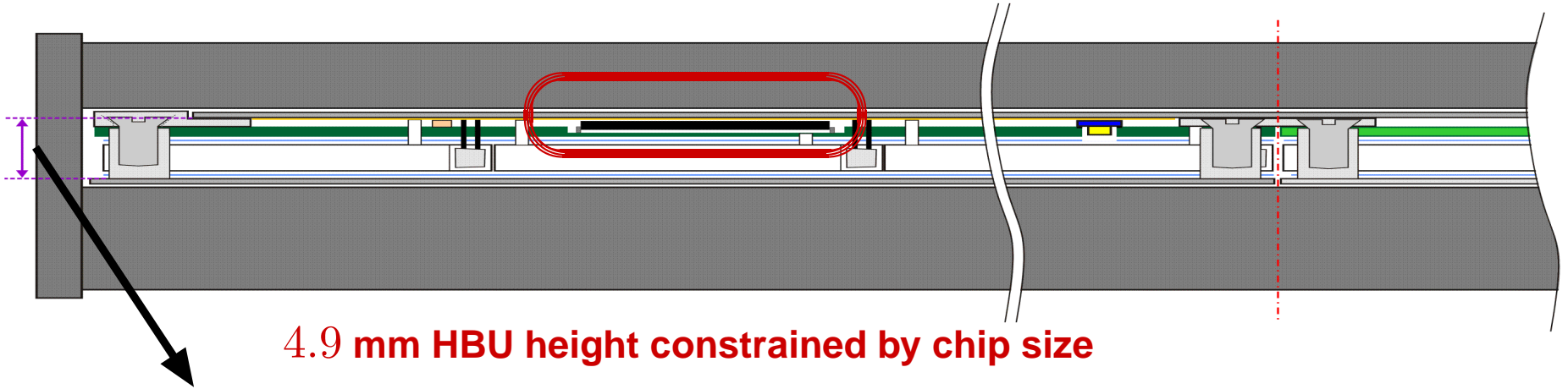
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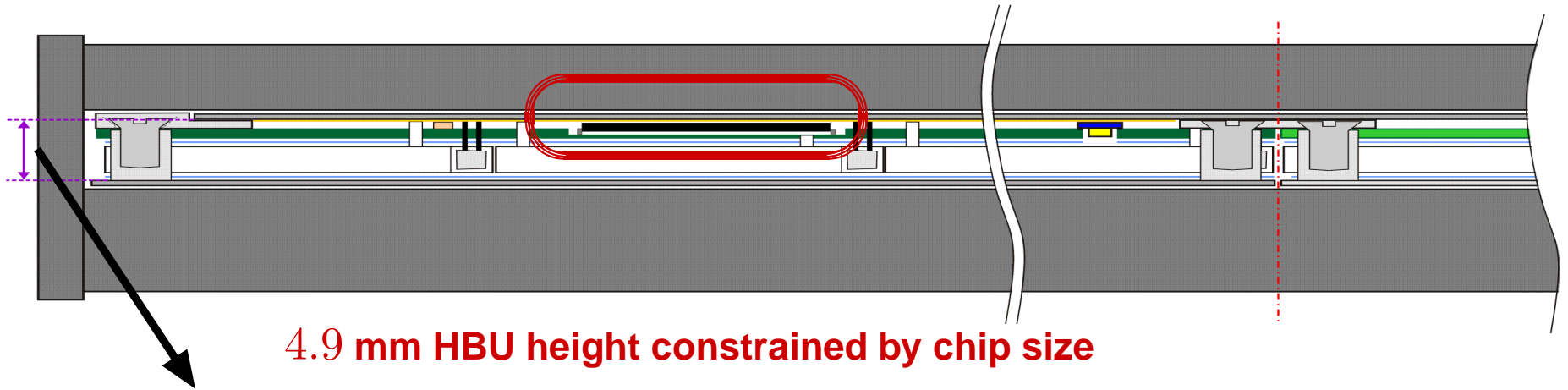
4.9 mm HBU height constrained by chip size

⇒ reduction obtained using SPIROC2 (with height 1.4 mm)

(SPIROC2 here shown with 1 mm; SPIROC1 = 4.3 mm)

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Power dissipation: cooling system not foreseen

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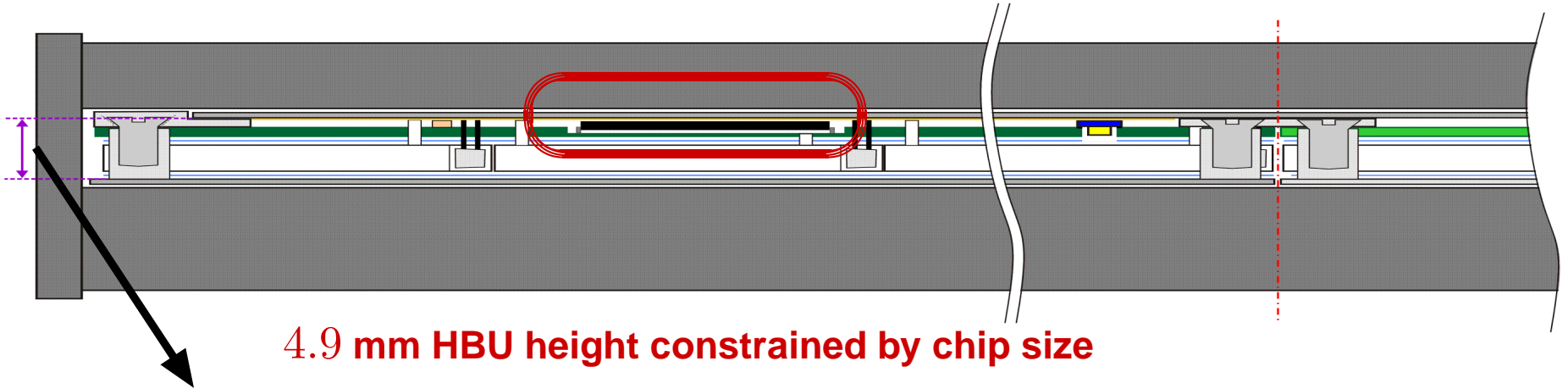
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— SPIROC: $25\mu\text{W}$

— calibration electronics: $23\mu\text{W}$

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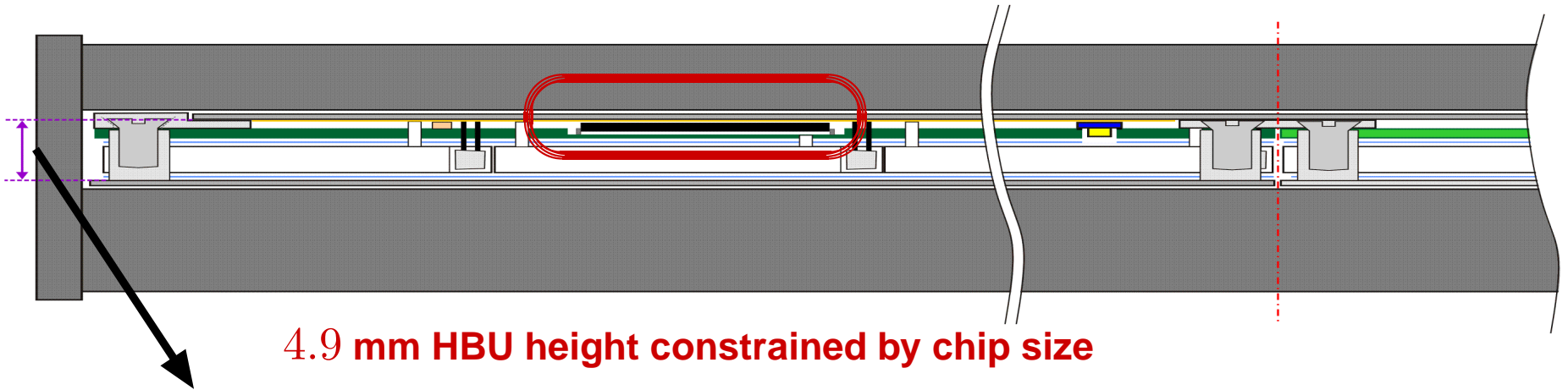
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between two ILC train crossing (on during 1% of ILC duty time)

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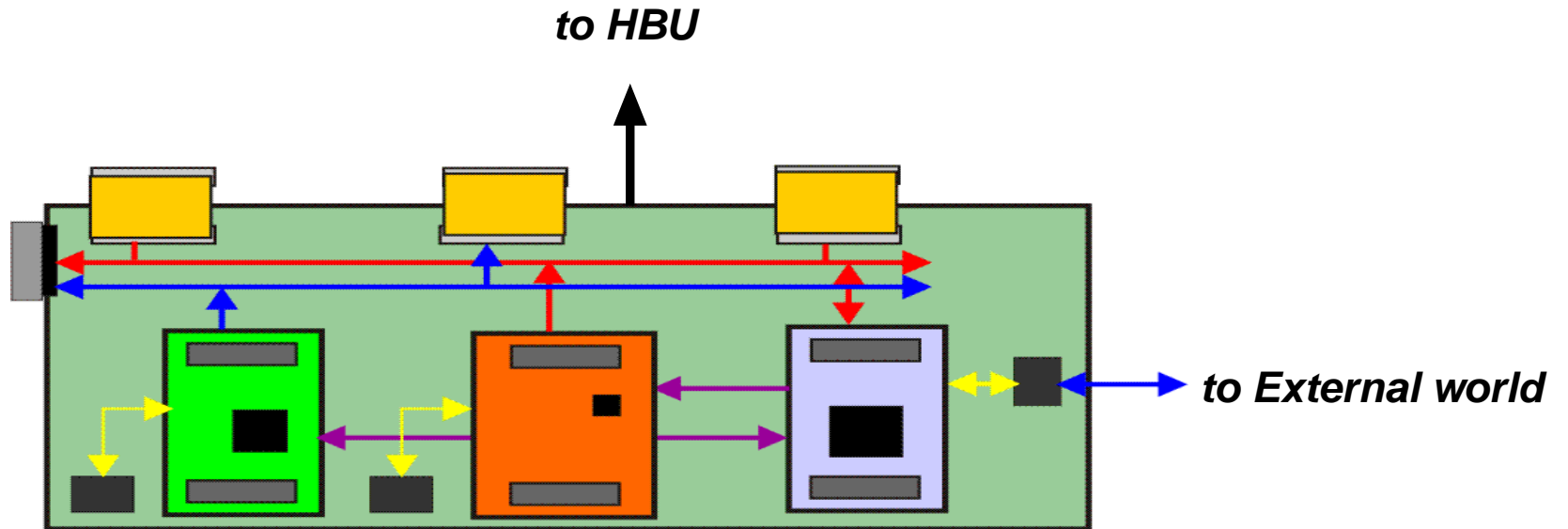
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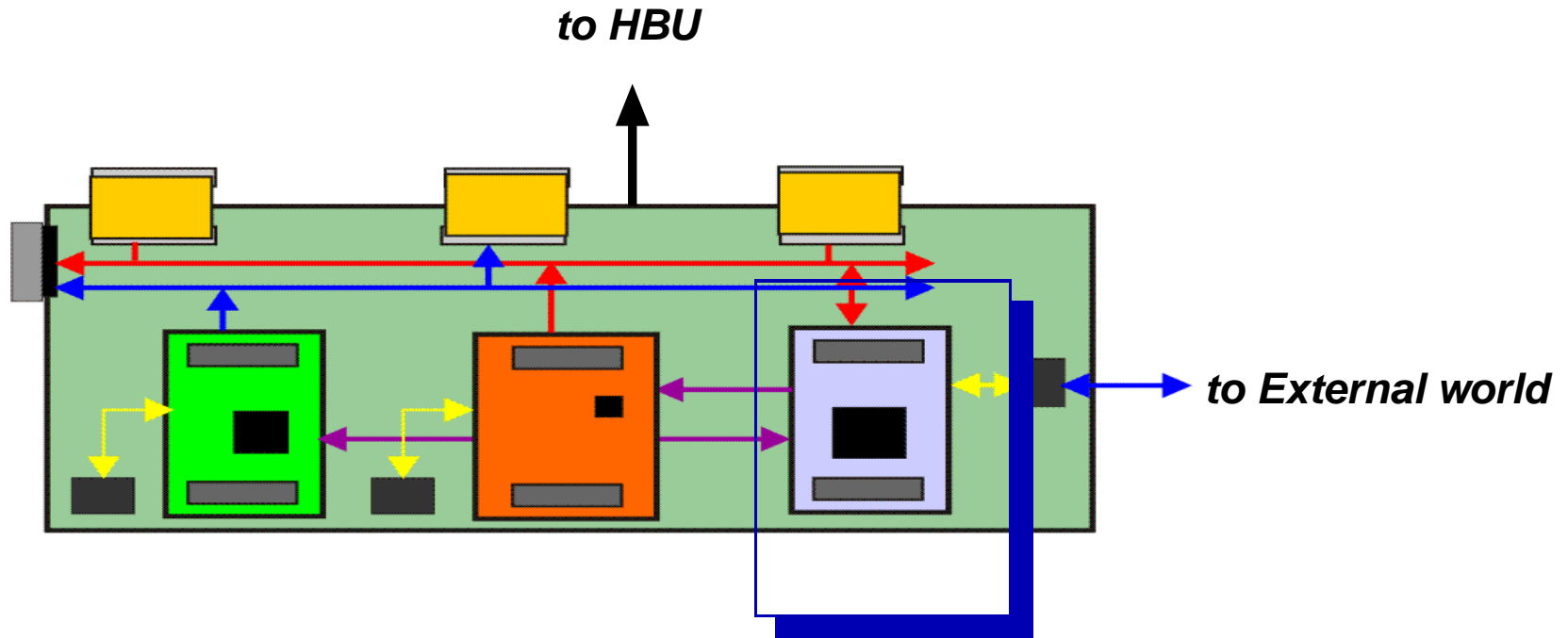
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✓ even more, considering calibrations done realistically only every few minutes

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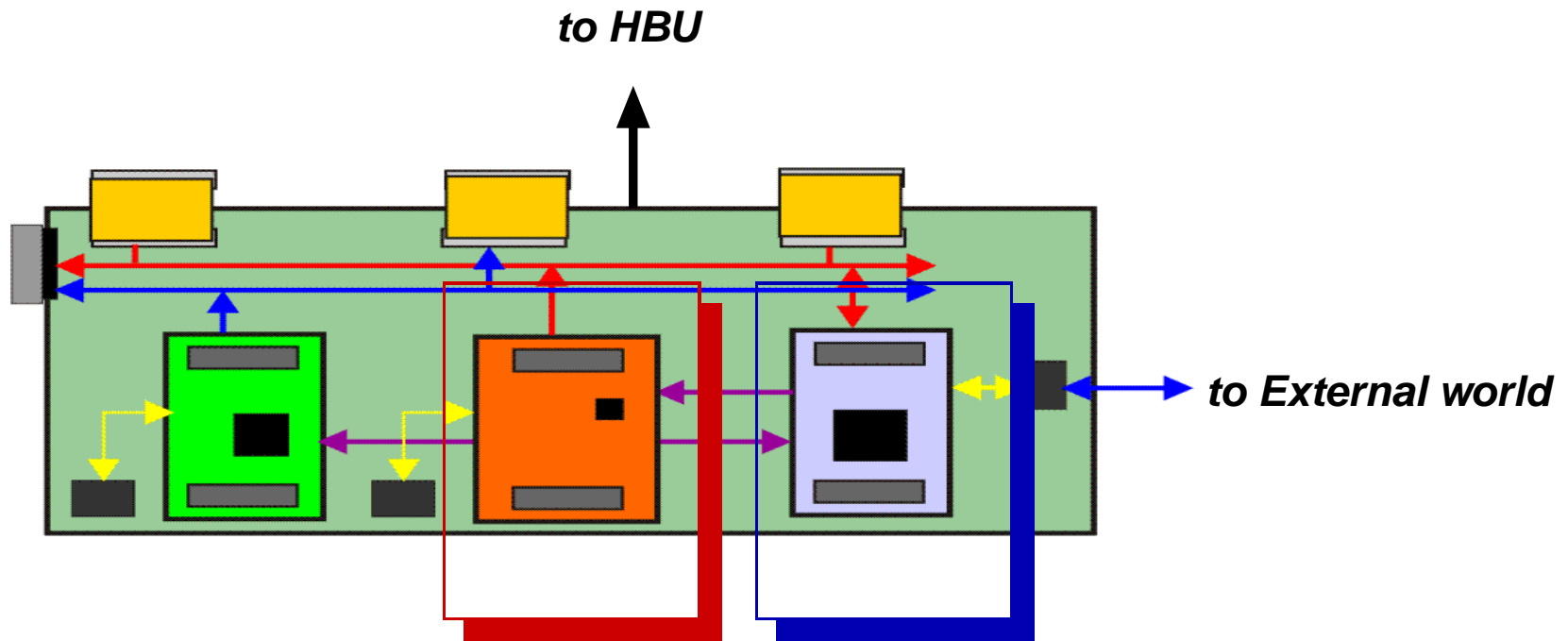
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DIF module

- External world ↔ HBU interface
- Readout/control of ASICs

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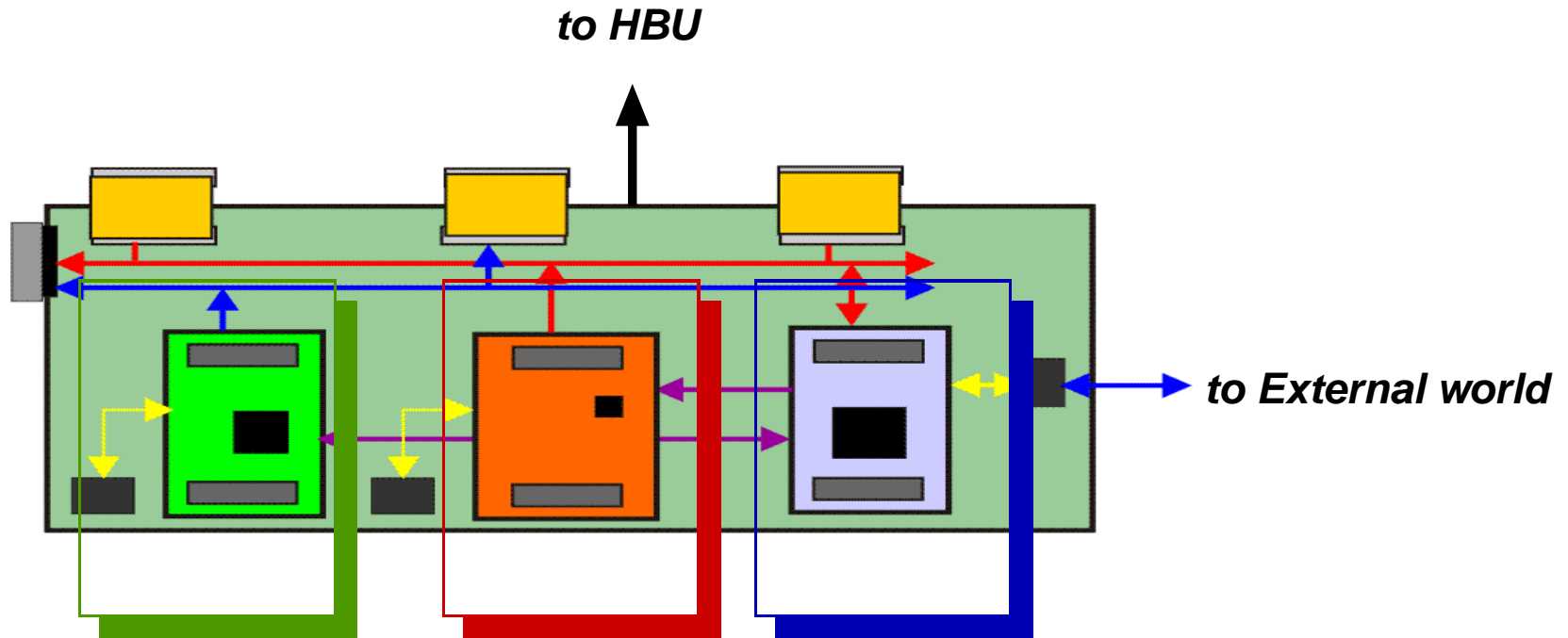
CALIB(ration) module

- Drives/regulates calibration electronics (LED + charge injection) inside HBUs

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POWER module

- Provides +3.5, +5 V, bias voltages & ground to HBUs (and SiPMs therein)

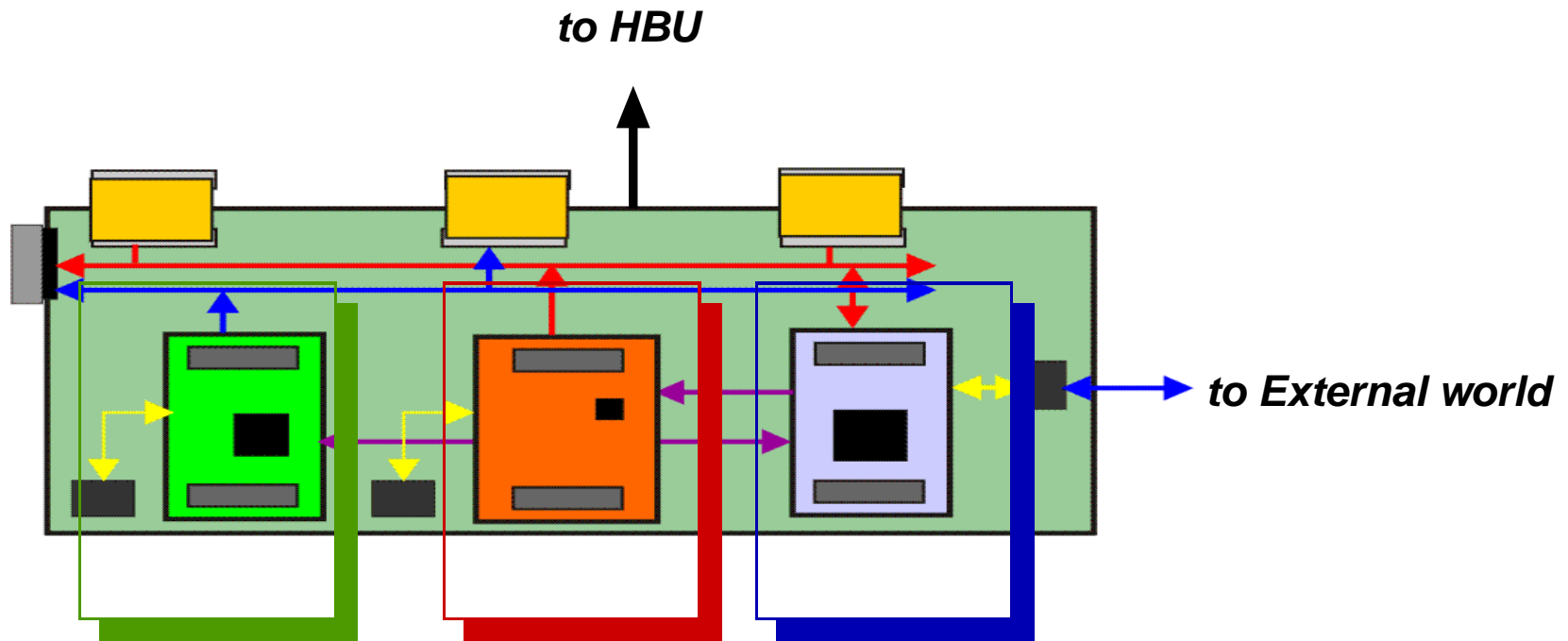
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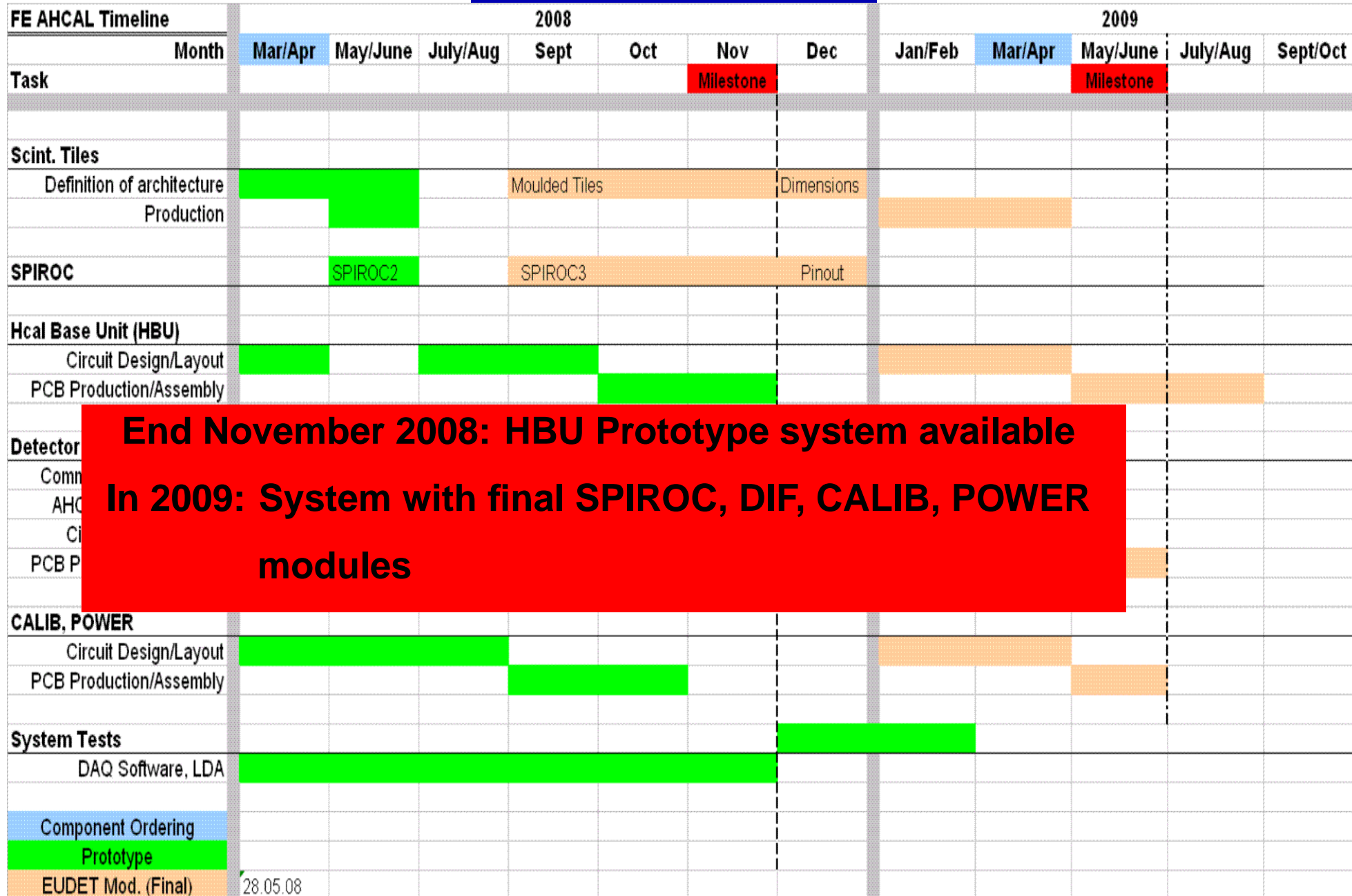
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🔴 Differently from HBU case, here cooling is foreseen (it is located outside detector)

Time Schedule

FE AHCAL Timeline		2008						2009				
Month	Mar/Apr	May/June	July/Aug	Sept	Oct	Nov	Dec	Jan/Feb	Mar/Apr	May/June	July/Aug	Sept/Oct
Task						Milestone				Milestone		
Scint. Tiles												
Definition of architecture	█			Moulded Tiles			Dimensions					
Production		█						█				
SPIROC												
		SPIROC2		SPIROC3			Pinout					
Hcal Base Unit (HBU)												
Circuit Design/Layout	█		█					█				
PCB Production/Assembly					█					█	█	
Detector Interface (DIF)												
Common Block Firmware	█		█									
AHCAL Block Firmware					█							
Circuit Design/Layout								█				
PCB Production/Assembly										█	█	
CALIB. POWER												
Circuit Design/Layout	█							█				
PCB Production/Assembly				█						█	█	
System Tests												
DAQ Software, LDA	█							█				
Component Ordering												
Prototype	█											
EUDET Mod. (Final)	28.05.08											

Time Schedule



End November 2008: HBU Prototype system available
In 2009: System with final SPIROC, DIF, CALIB, POWER modules

Summary and Outlook

● SPIROC (to readout) commissioning on going

⇒ DESY+Heidelberg+LAL synergy

⇒ SPIROC2 design done; chip expected for end 2008

● Electronic unit HBU design in advanced stage

⇒ module size driven by SPIROC height (reduced with SPIROC2)

⇒ power dissipation optimized

— switching off SPIROC/calibration electronics when not needed

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● Time schedule for design and production of component prototypes ready

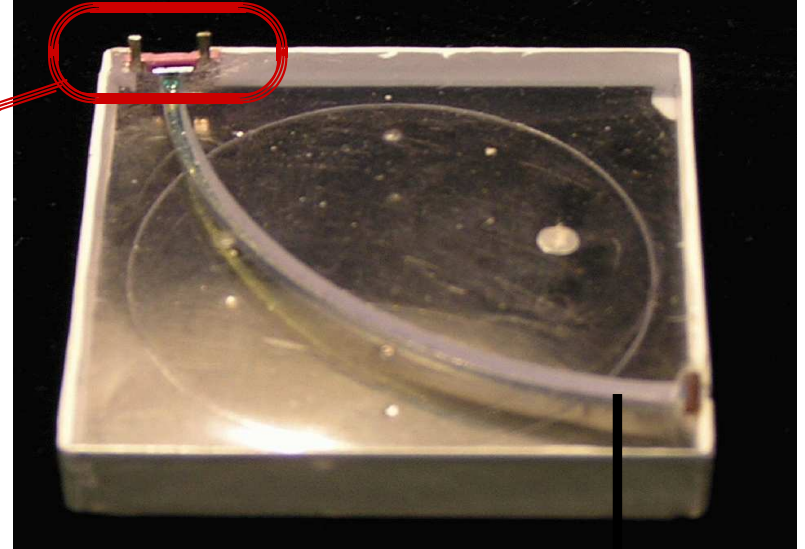
⇒ first version of all components expected by end of 2008

⇒ final version of system expected within 2009

Back Slides

SiPM/Scintillator Characteristics

SiPM: novel multi-pixel photo-multiplier
operated in Geiger mode
⇒ B -field proof, small

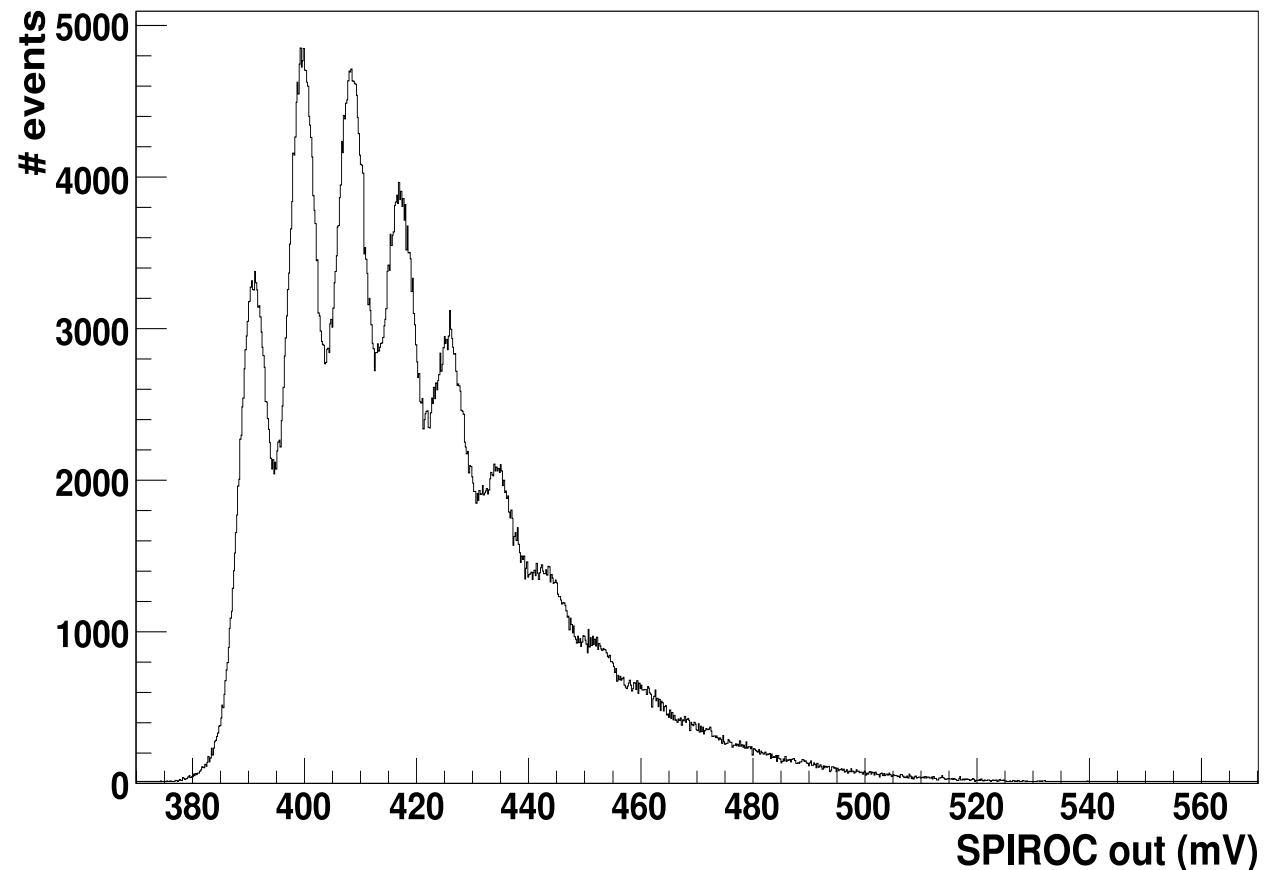


Optimization of scintillator size to $3 \times 3 \text{ cm}^2$
⇒ confirmed by Monte Carlo simulation

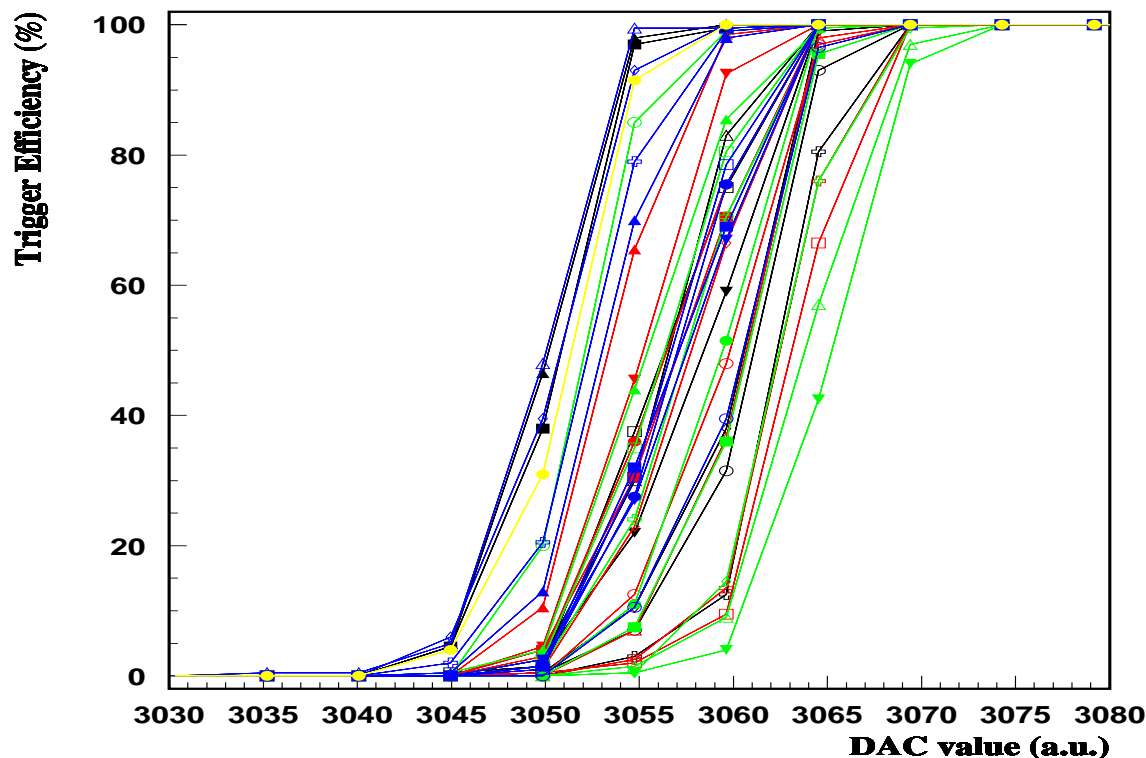
Wavelength shifter

SiPM: Single-peak spectrum with External Trigger

- SiPM Nr. 753
- SPIOC operated in HG mode with 100 fF variable capacitance and 25 ns shaping time
- external hold (from pulse generator)

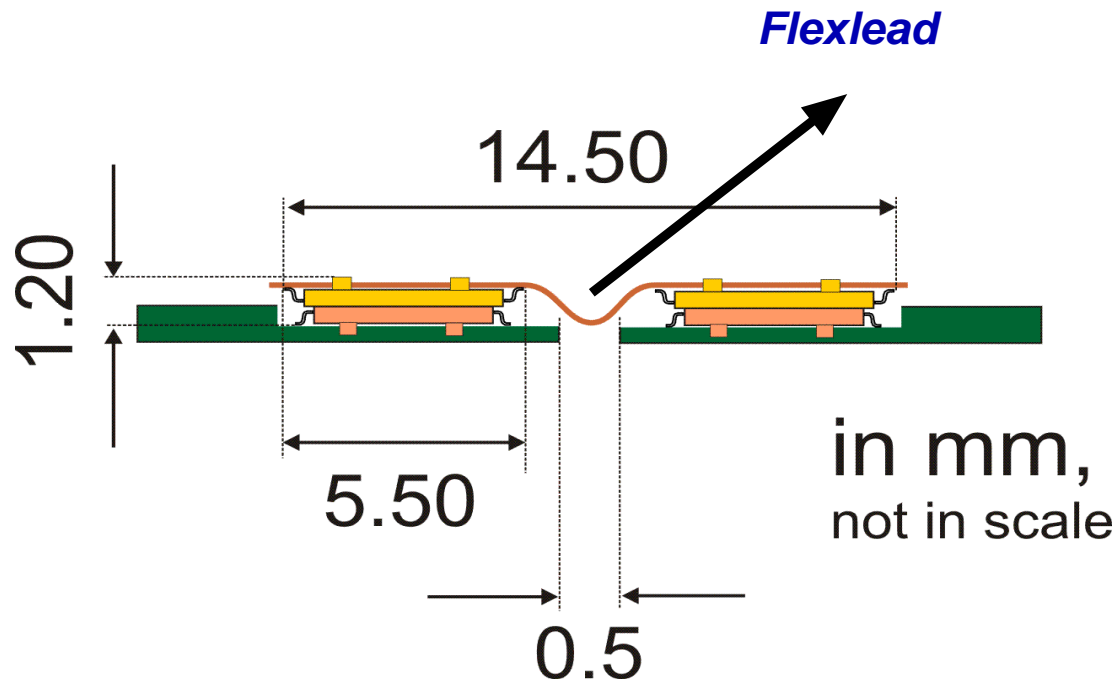


SPIROC: Noise Measurements



- Noise measured for all 36 input channels, separately, by counting the trigger efficiency while decreasing the voltage reference at the discriminator in SPIROC

HBU-HBU Interconnection



Flexlead:

- rigid at connector (80 pins) sides
- flexible in between HBUs
- bended flexlead allows HBU-HBU displacement of $\pm 100\mu\text{m}$